

COMPAL CONFIDENTIAL

MODEL NAME : *BDW00*
COMPAL P/N : *DA8DW00L100*
PCB NO : *LA-1452*
Revision : *1.0*
DATE :

Abacus/TangII Schematics Document
uFCBGA/uFCPGA Northwood

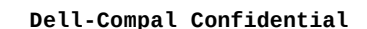
2002-11-26
REV: 1.0

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Title			
Cover Sheet			
Size	Document Number		Rev
	Abacus/TangII LA-1452		1.0
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File Name : LA-1452



Block Diagram

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Revision List

	Schematics Rev	PCB Rev	CHIPS Rev
SST-Build	0.1	0.1	
PT-Build	0.2	0.2	845PE Rev B0 845GL Rev B1 ICH4 Rev B0
ST-Build			
QT-Build			

Ceramic Capacitor Spec Guide:

Temperature Characteristics:

Symbol	0	1	2	3	4	5	6	7
CODE	Z5U	Z5V	Z5P	Y5U	Y5V	Y5P	X5R	X7R

8	9	A	B	C	D	E	F	G
NP0	C0G		BJ	CH	CJ	CK	SH	SJ

H	I	J	
UJ	UK	SL	

Tolerance:

Symbol	A	B	C	D	F	G	H	J
CODE	+-.05PF	+-.0.1PF	+-.0.25PF	+-.0.5PF	+-.1PF	+-.2%	+-.3%	+-.5%

K	M	N	P	Q	V	X	Z	
+-.10%	+-.20%	+-.30%	+100, -0%	+30, -10%	+20, -10%	+40, -20%	+80, -20%	

SMBUS Control Table

	SOURCE	INVERTER	BATT	SERIAL EEPROM	THERMAL SENSOR (CPU) (U57)	THERMAL SENSOR (U25/U23)	SODIMM	CLK CHIP	MINI PCI
SMB_EC_CK1 SMB_EC_DA1	NS 87591	✓	✓	✓ (1010)	✗	✗	✗	✗	✗
SMB_EC_CK2 SMB_EC_DA2	NS 87591	✗	✗	✗	✓	✓	✗	✗	✗
SMB_CLK SMB_DATA	ICH4	✗	✗	✗	✗	✗	✓	✓	✓

Power Managment table

Signal State	+3VALW +5VALW +12VALW	+3V +5V +2.5V	+3VS +5VS +1.5VS +1.2VP +CPU_CORE +1.25VS
S0	ON	ON	ON
S1	ON	ON	ON
S3	ON	ON	OFF
S5 S4/AC	ON	OFF	OFF
S5 S4/AC don't exist	OFF	OFF	OFF

NOTE1:

@XX : Depop component

1@XX : Pop for INT, Depop for EXT

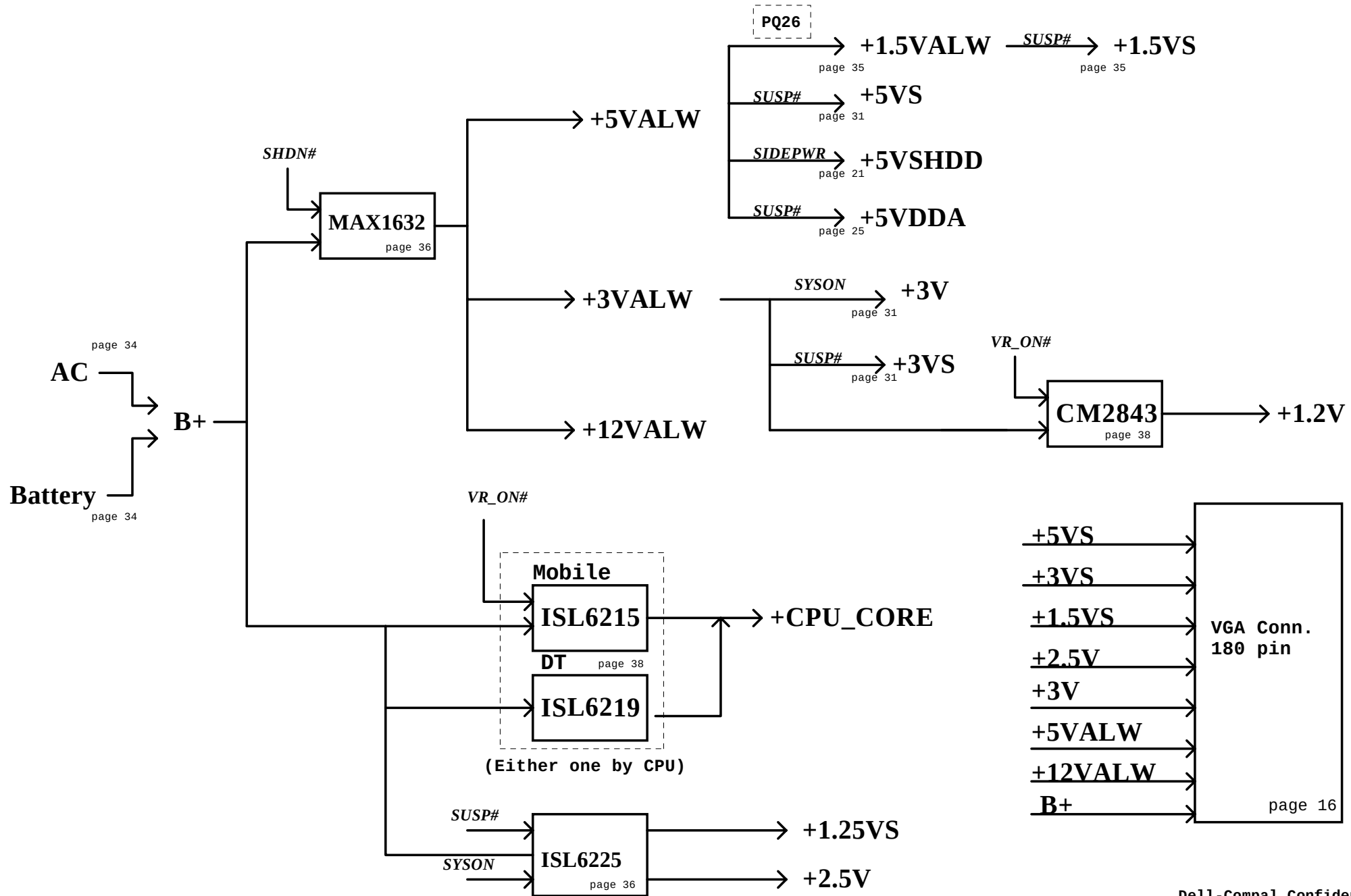
2@XX : Pop for EXT, Depop for INT

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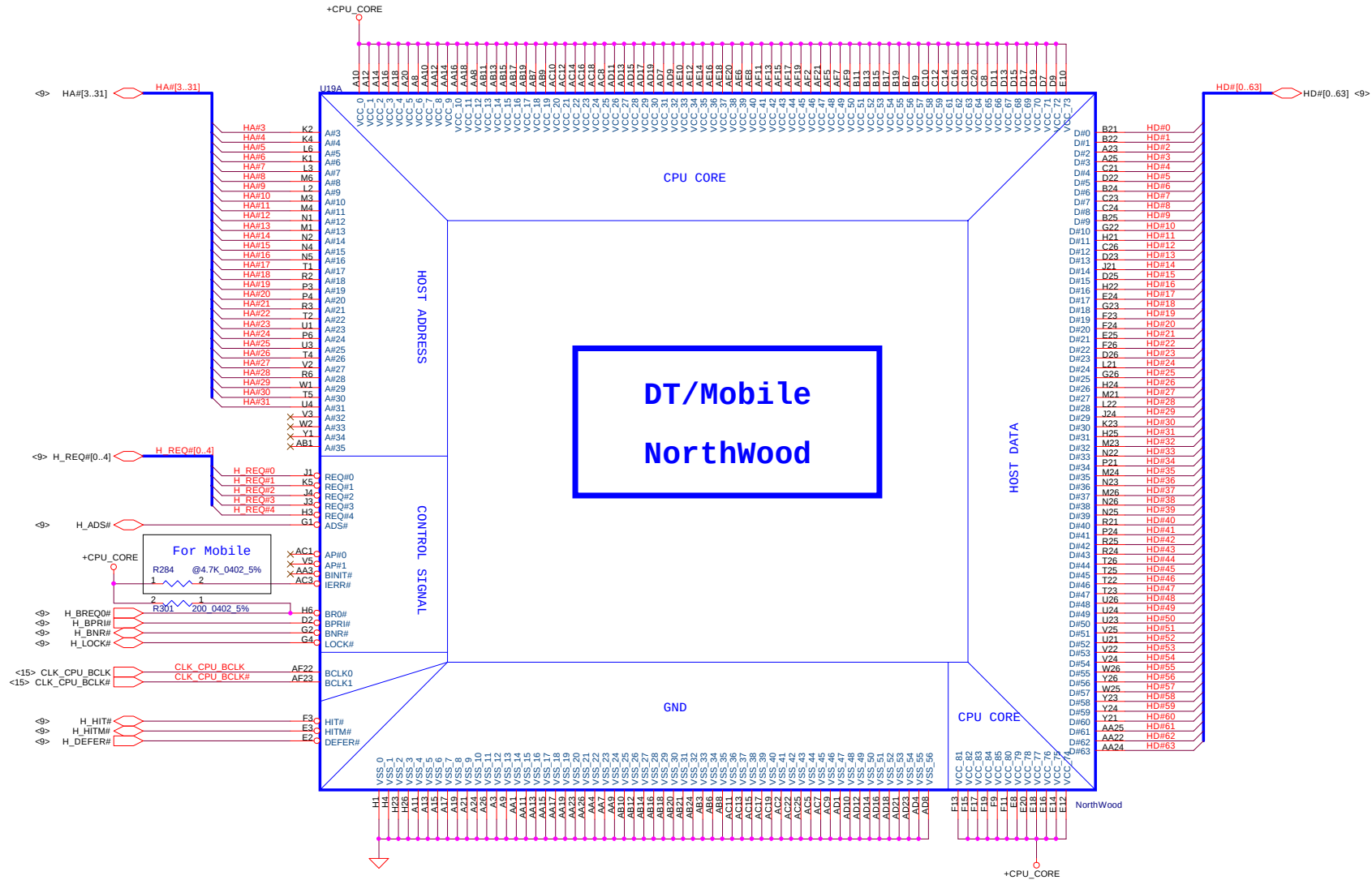
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Title POWER DIAGRAM			
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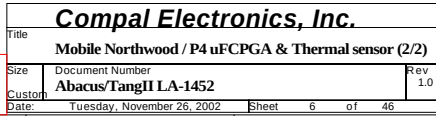
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Northwood / P4 uFCPGA (1/2)

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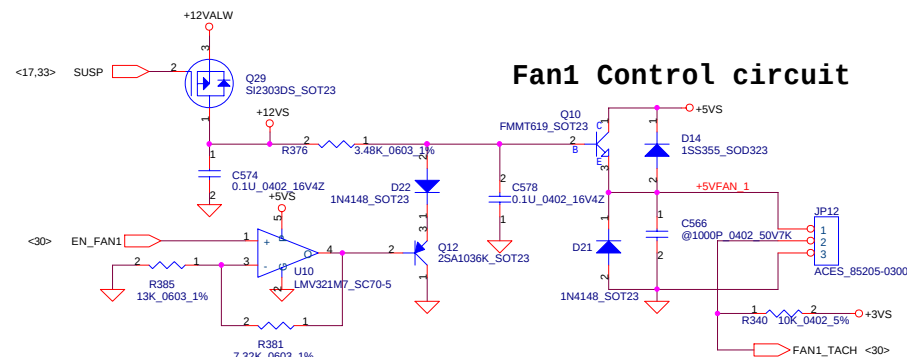
Place close to CPU, Use 2-3 vias per PAD.
Place .22uF caps underneath balls on solder side.
Place 10uF caps on the peripheral near balls.
Use 2-3 vias per PAD.

Place close to CPU power and ground pin as possible (<1inch)

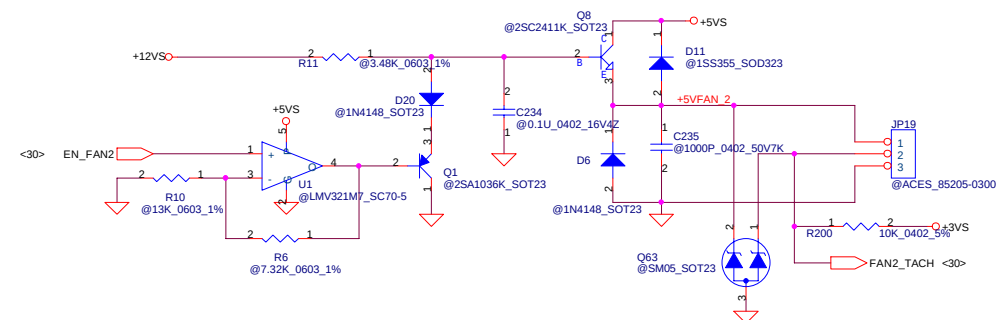
For Mobile's CPU:
ESR total=1.875m ohm
C total=2590uF

PLACE ON CPU SIDE

The diagram shows a series of capacitors connected between the +CPU_CORE and GND lines. The capacitors are labeled C104, C111, C113, C117, C119, C120, C110, C112, C116, and C118. Each capacitor is connected to the +CPU_CORE line on one side and the GND line on the other. The capacitors are labeled with their values: 0.22uF 0603 10V7K. The diagram is titled "PLACE ON CPU SIDE" in blue text.



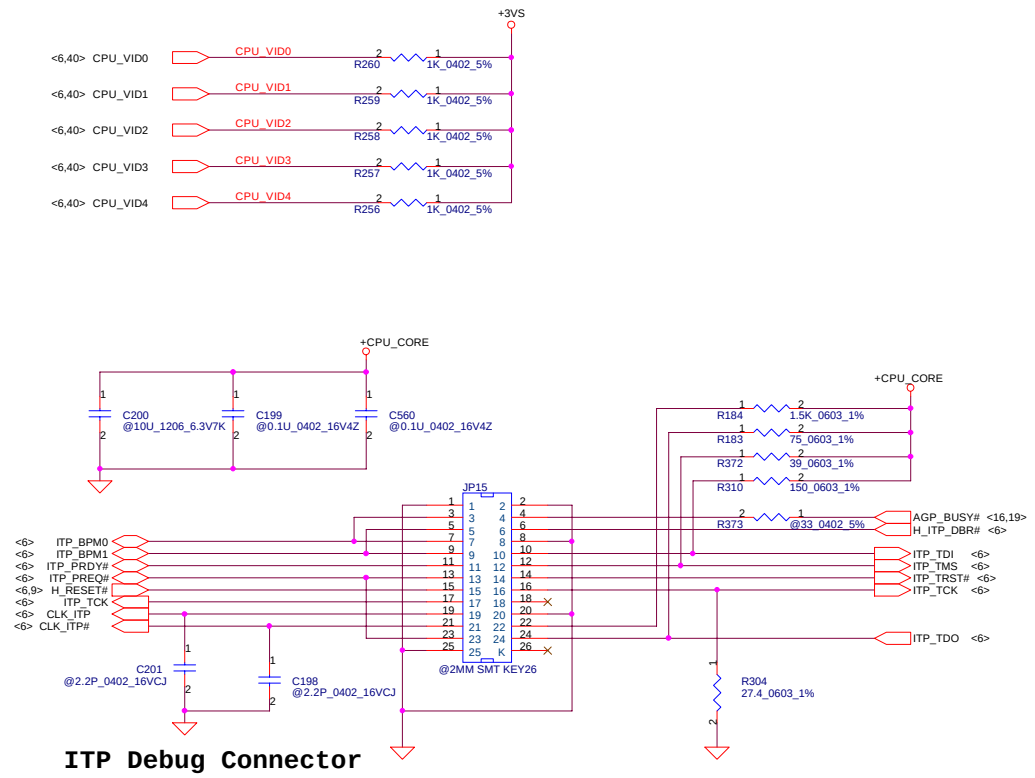
Fan2 Control circuit



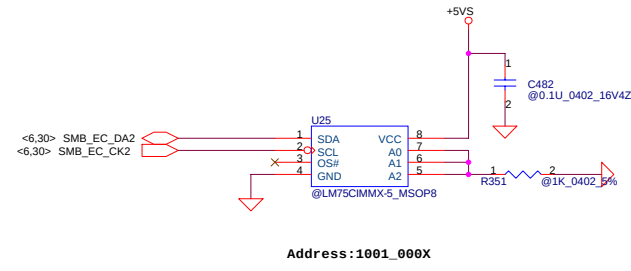
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Title	CPU Decoupling CAP. & Fan control			Rev	1.0
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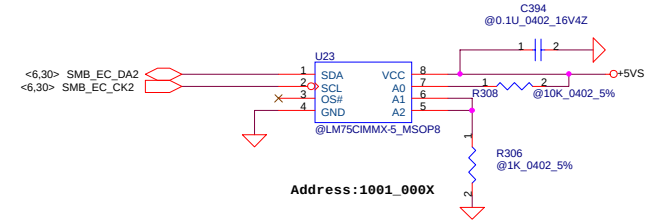
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ITP Debug Connector



Address:1001_000X



Address:1001_000X

M0/DT_CPU	Mobile CPU					Desktop CPU				
	1					0				
VID	4	3	2	1	0	4	3	2	1	0
VCC										
1.750V	0	0	0	0	0	0	0	1	0	0
1.700V	0	0	0	0	1	0	0	1	1	0
1.650V	0	0	0	1	0	0	1	0	0	0
1.600V	0	0	0	1	1	0	1	0	1	0
1.550V	0	0	1	0	0	0	1	1	0	0
1.500V	0	0	1	0	1	0	1	1	1	0
1.450V	0	0	1	1	0	1	0	0	0	0
1.400V	0	0	1	1	1	1	0	0	1	0
1.350V	0	1	0	0	0	1	0	1	0	0
1.300V	0	1	0	0	1	1	0	1	1	0
1.250V	0	1	0	1	0	1	1	0	0	0
1.200V	0	1	0	1	1	1	1	0	1	0
1.150V	0	1	1	0	0	1	1	1	0	0
1.100V	0	1	1	0	1	1	1	1	1	0
1.050V	0	1	1	1	0	X	X	X	X	X
1.000V	0	1	1	1	1	X	X	X	X	X
0.975V	1	0	0	0	0	X	X	X	X	X
0.950V	1	0	0	0	1	X	X	X	X	X
0.925V	1	0	0	1	0	X	X	X	X	X
0.900V	1	0	0	1	1	X	X	X	X	X
0.875V	1	0	1	0	0	X	X	X	X	X
0.850V	1	0	1	0	1	X	X	X	X	X
0.825V	1	0	1	1	0	X	X	X	X	X
0.800V	1	0	1	1	1	X	X	X	X	X
0.775V	1	1	0	0	0	X	X	X	X	X
0.750V	1	1	0	0	1	X	X	X	X	X
0.725V	1	1	0	1	0	X	X	X	X	X
0.700V	1	1	0	1	1	X	X	X	X	X
0.675V	1	1	1	0	0	X	X	X	X	X
0.650V	1	1	1	0	1	X	X	X	X	X
0.625V	1	1	1	1	0	X	X	X	X	X
0.600V	1	1	1	1	1	X	X	X	X	X
VRM output off						1	1	1	1	1

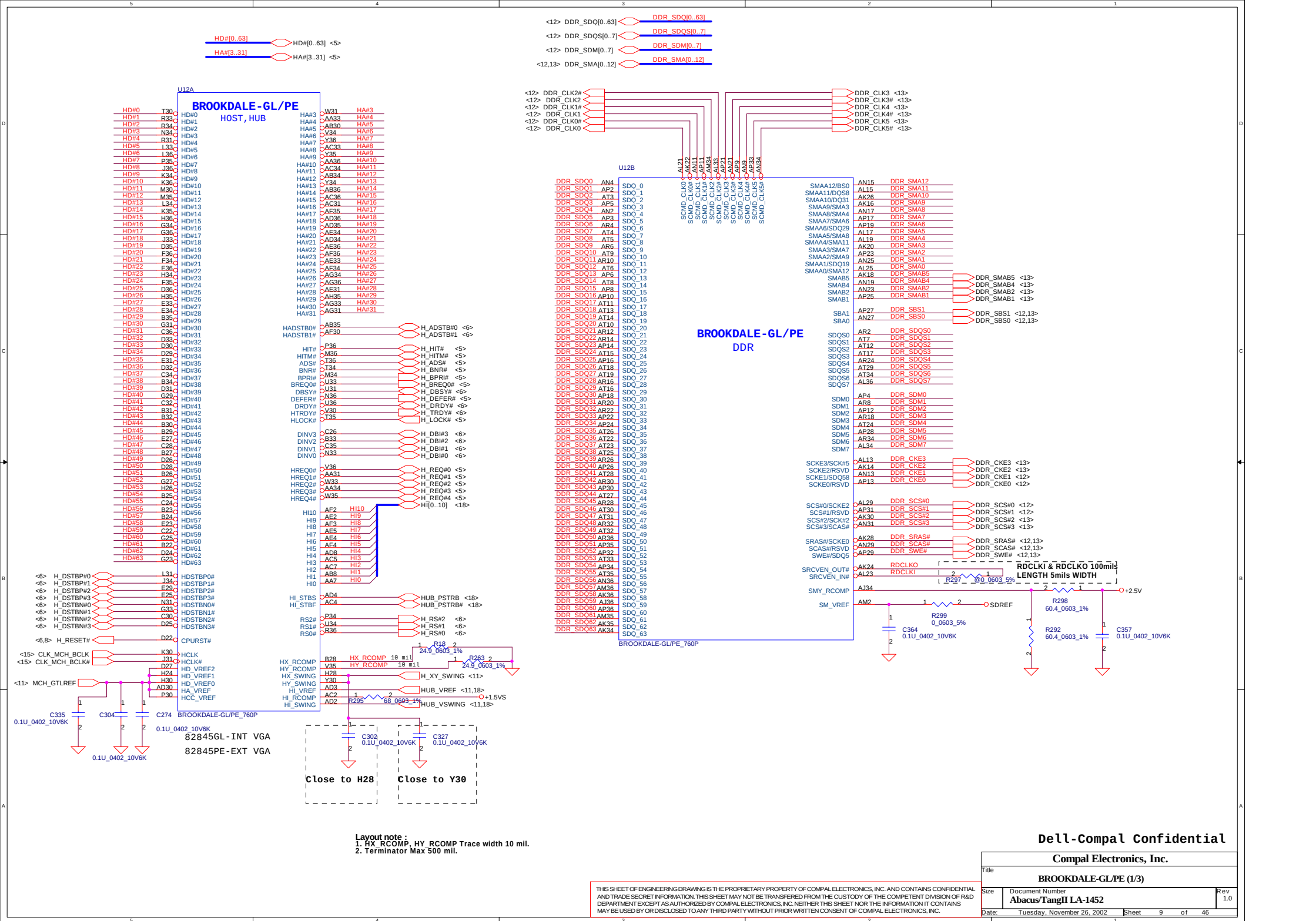
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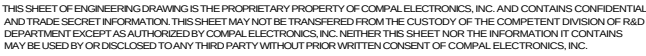
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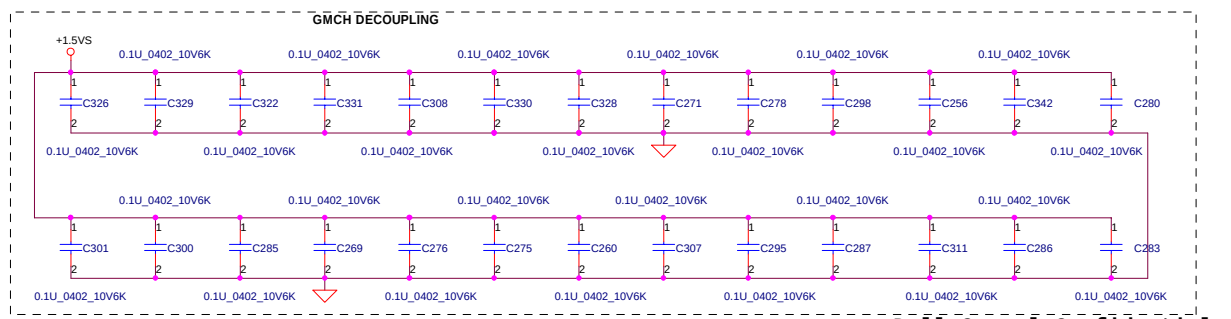
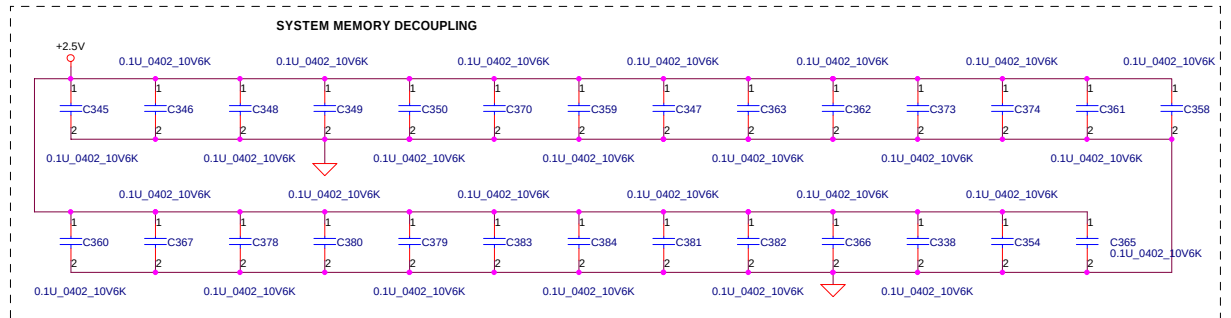
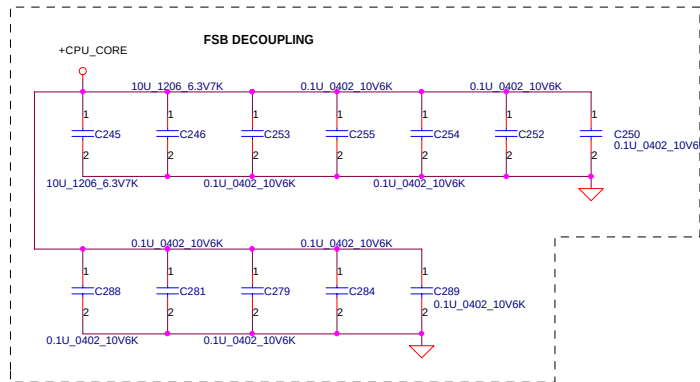
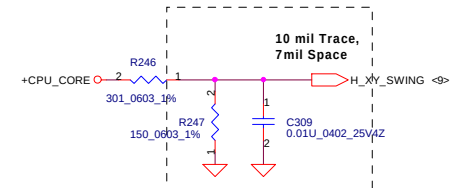
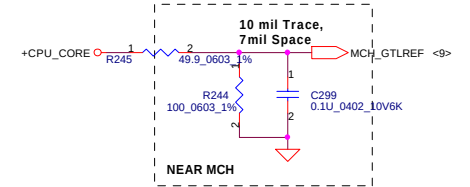
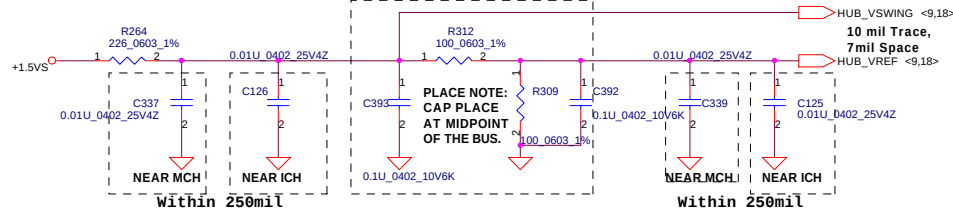
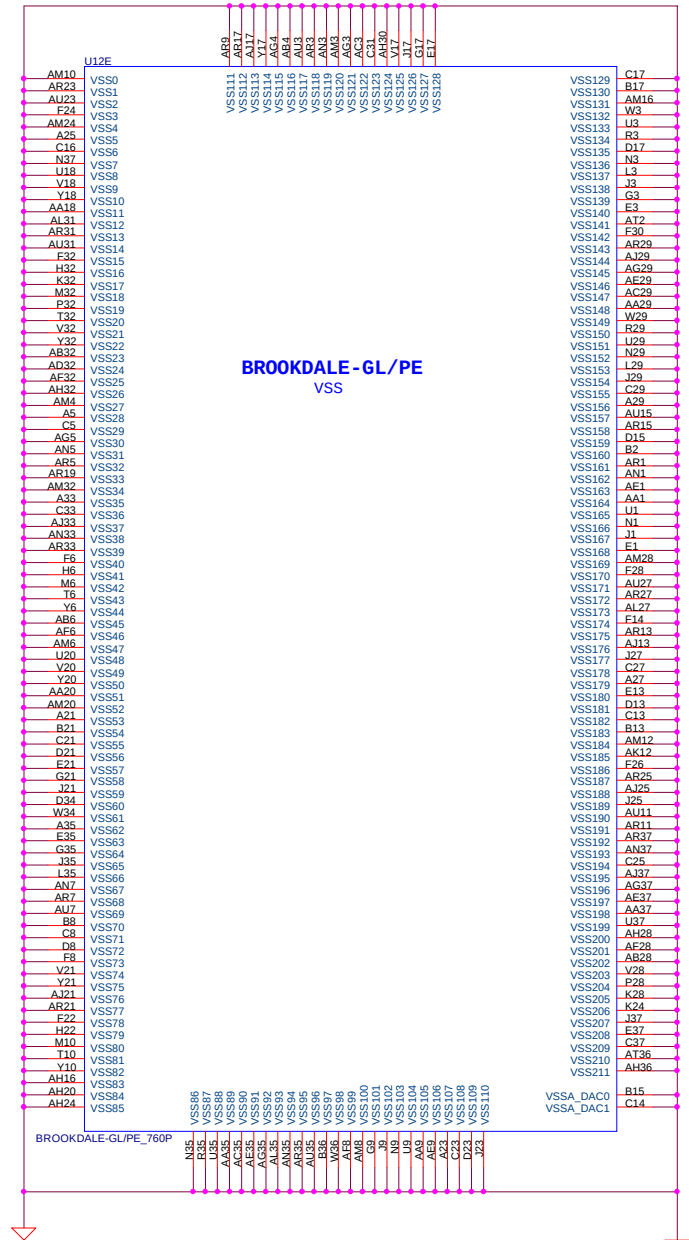
CPU VID & ITP PORT

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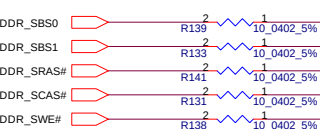
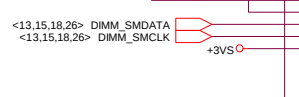
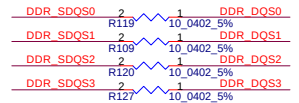




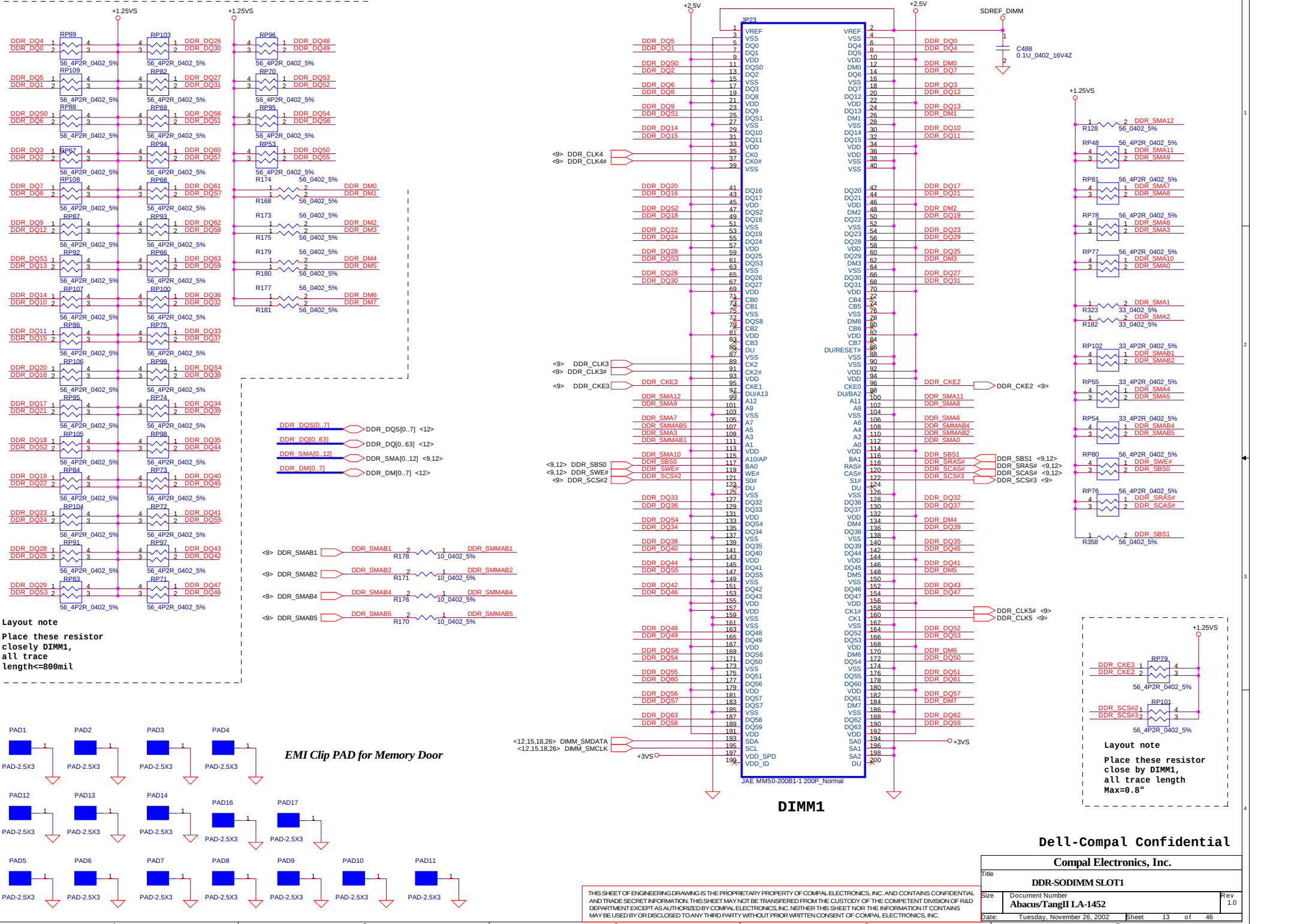
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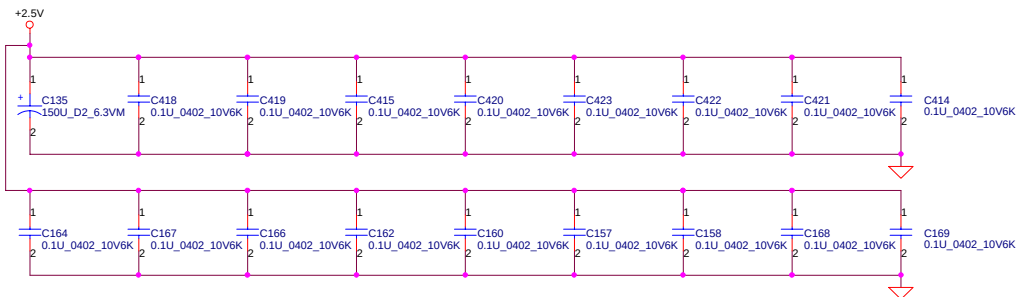


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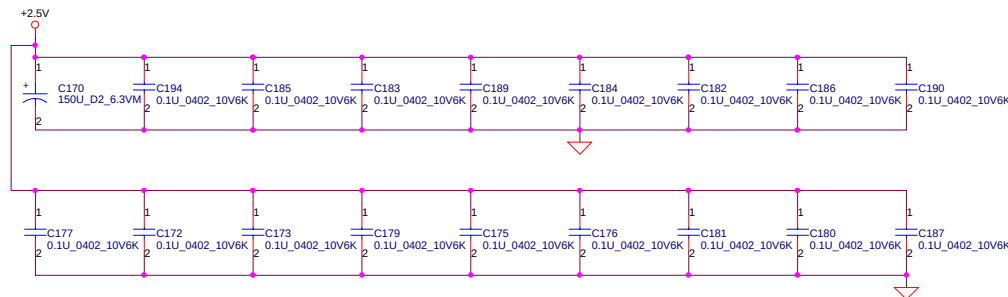


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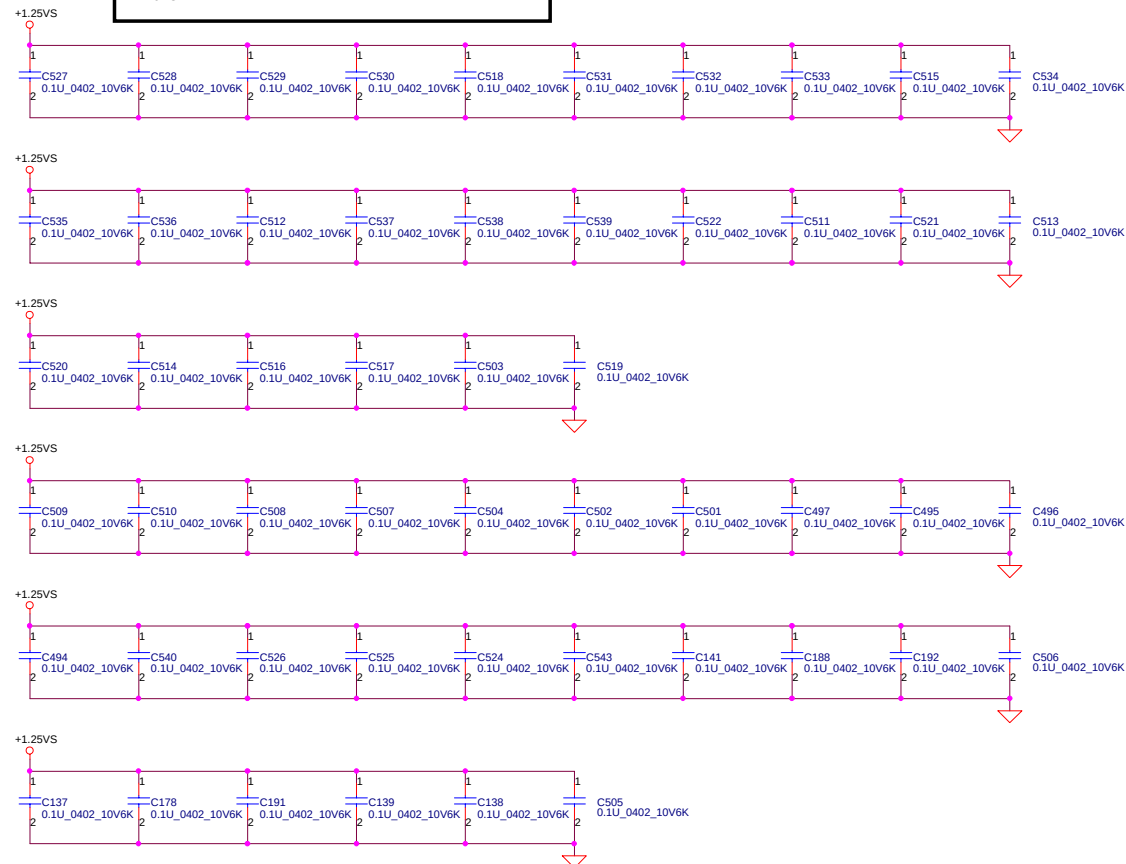
Layout note :
Distribute as close as possible
to DDR-SODIMM0.



Layout note :
Distribute as close as possible
to DDR-SODIMM1.



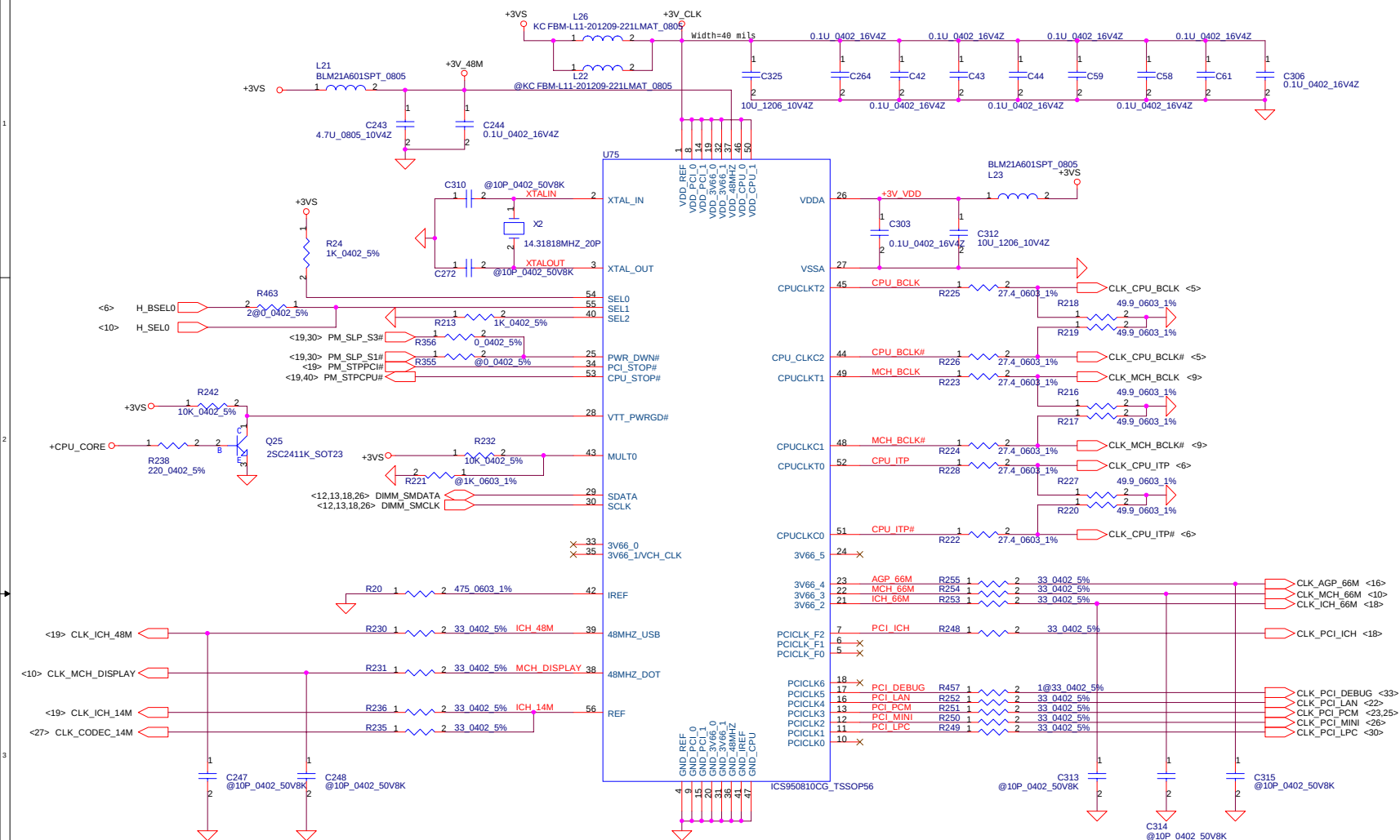
Layout note :
Place one cap close to every 2 pull up resistors termination to
+1.25VS



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Title			
DDR SODIMM Decoupling			
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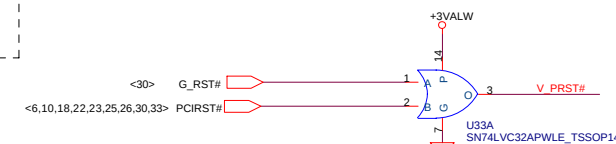
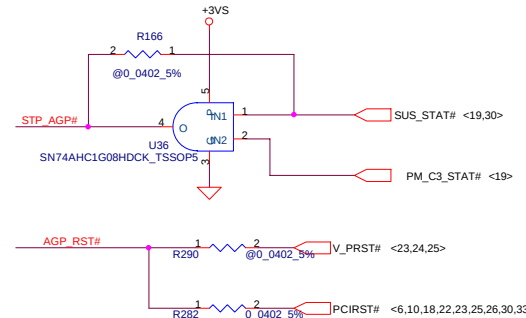
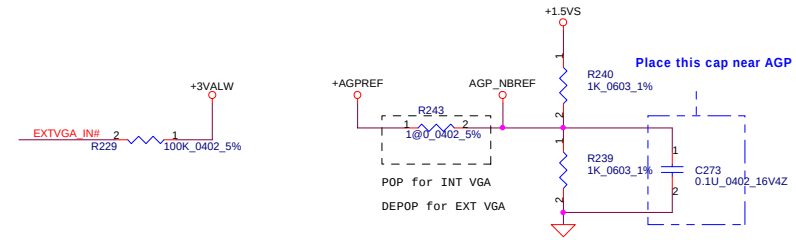
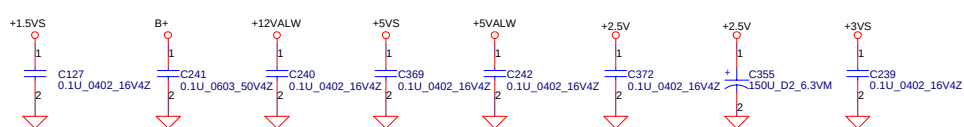
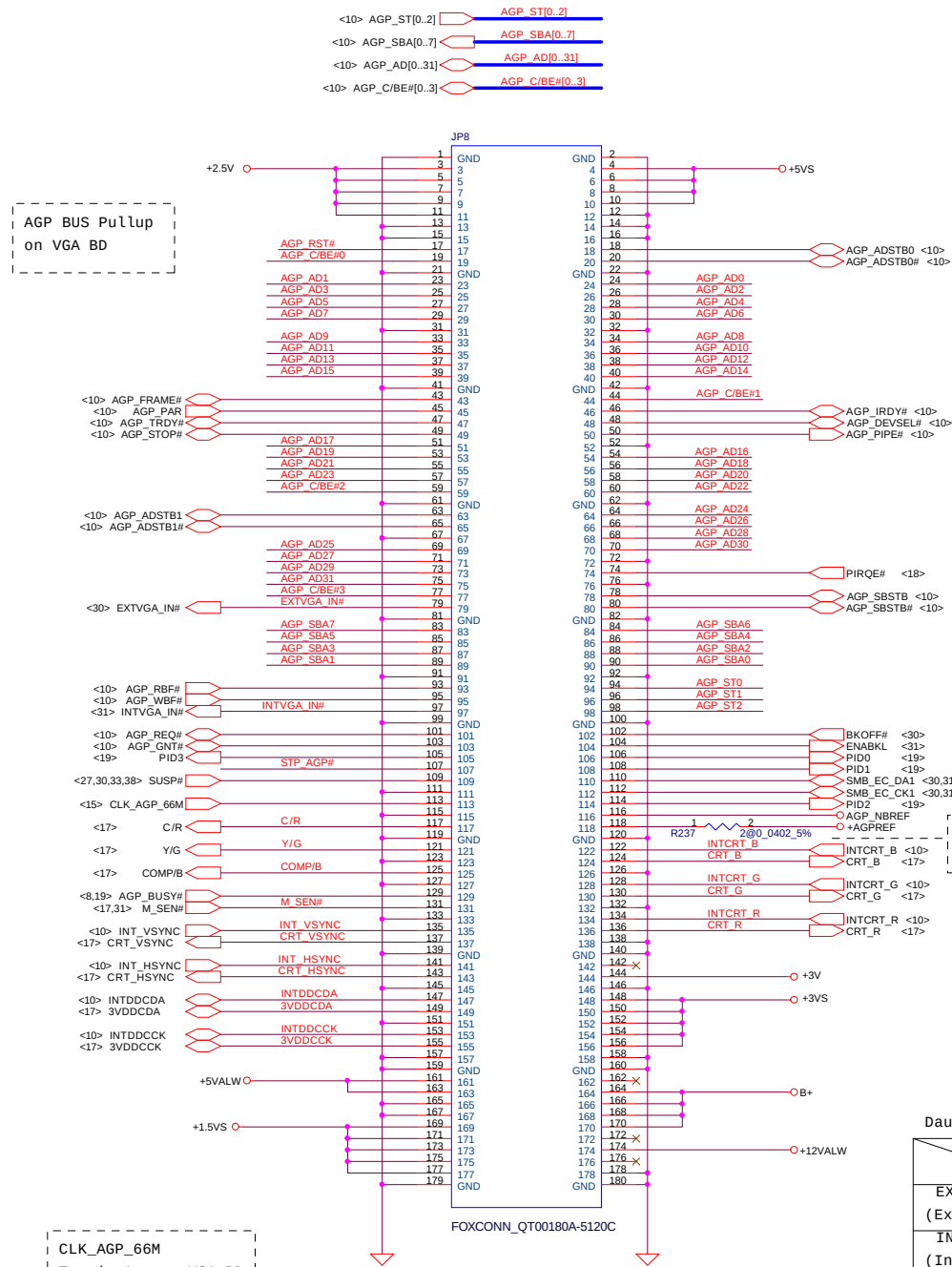
CPU Frequency Select Table

SEL[2:0]	CK-408 Speed
001	100 MHZ
011	133 MHZ

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Clock Generator			
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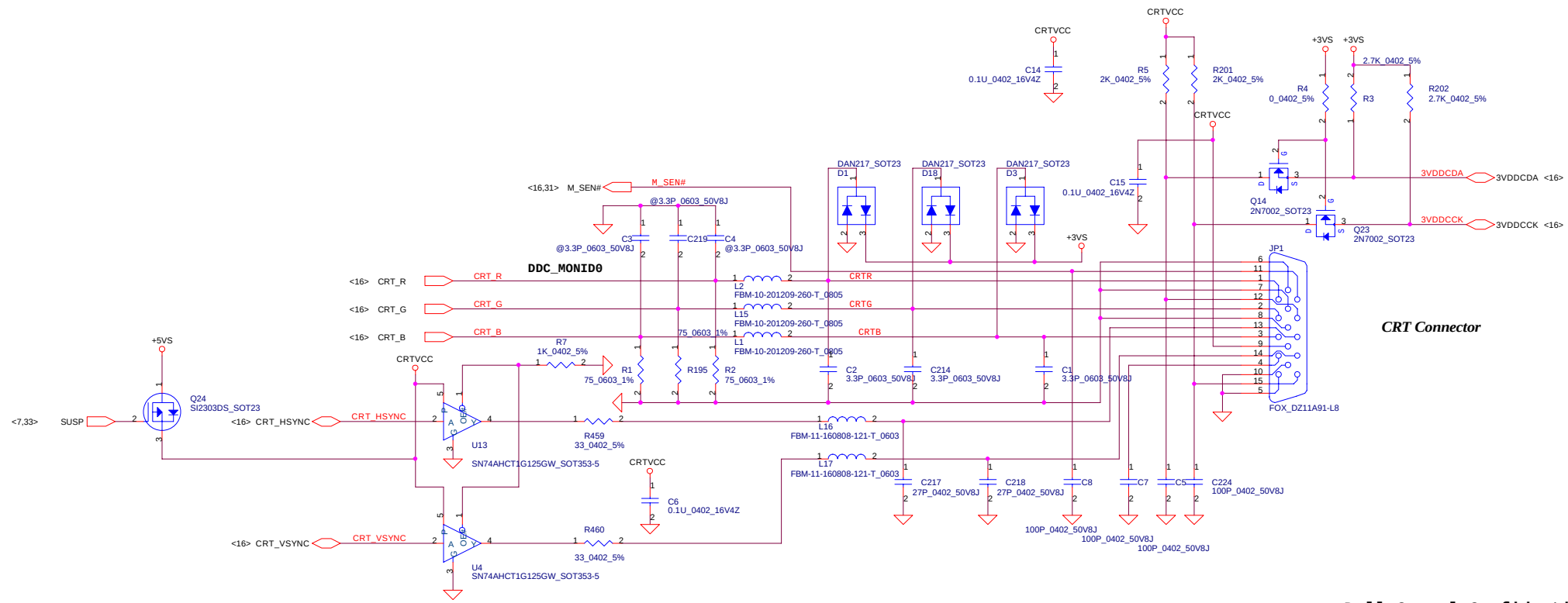
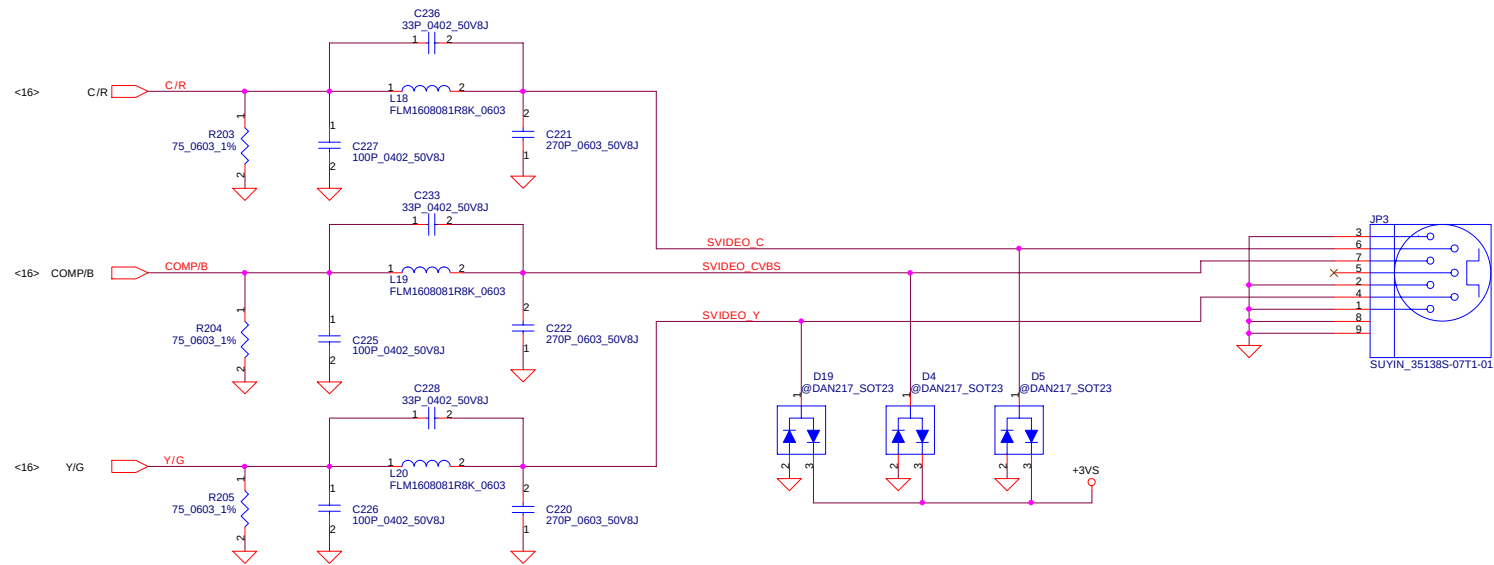
Daughter Card Present Table

	DOCKED	NON DOCKED
EXTVGA_IN# (Ext. Graphy)	LOW	HIGH
INTVGA_IN# (Int. Graphy)	LOW	HIGH

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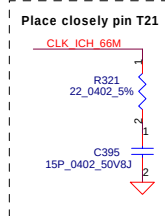
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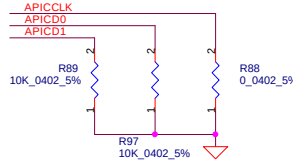
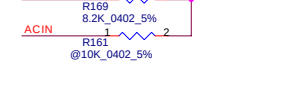
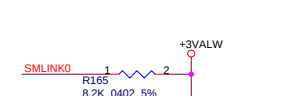
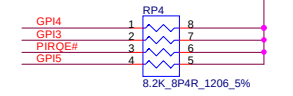
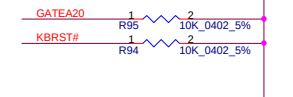
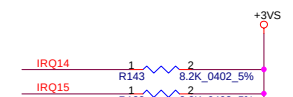
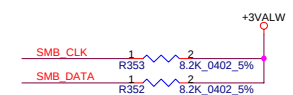
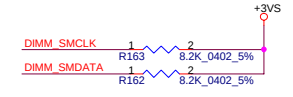
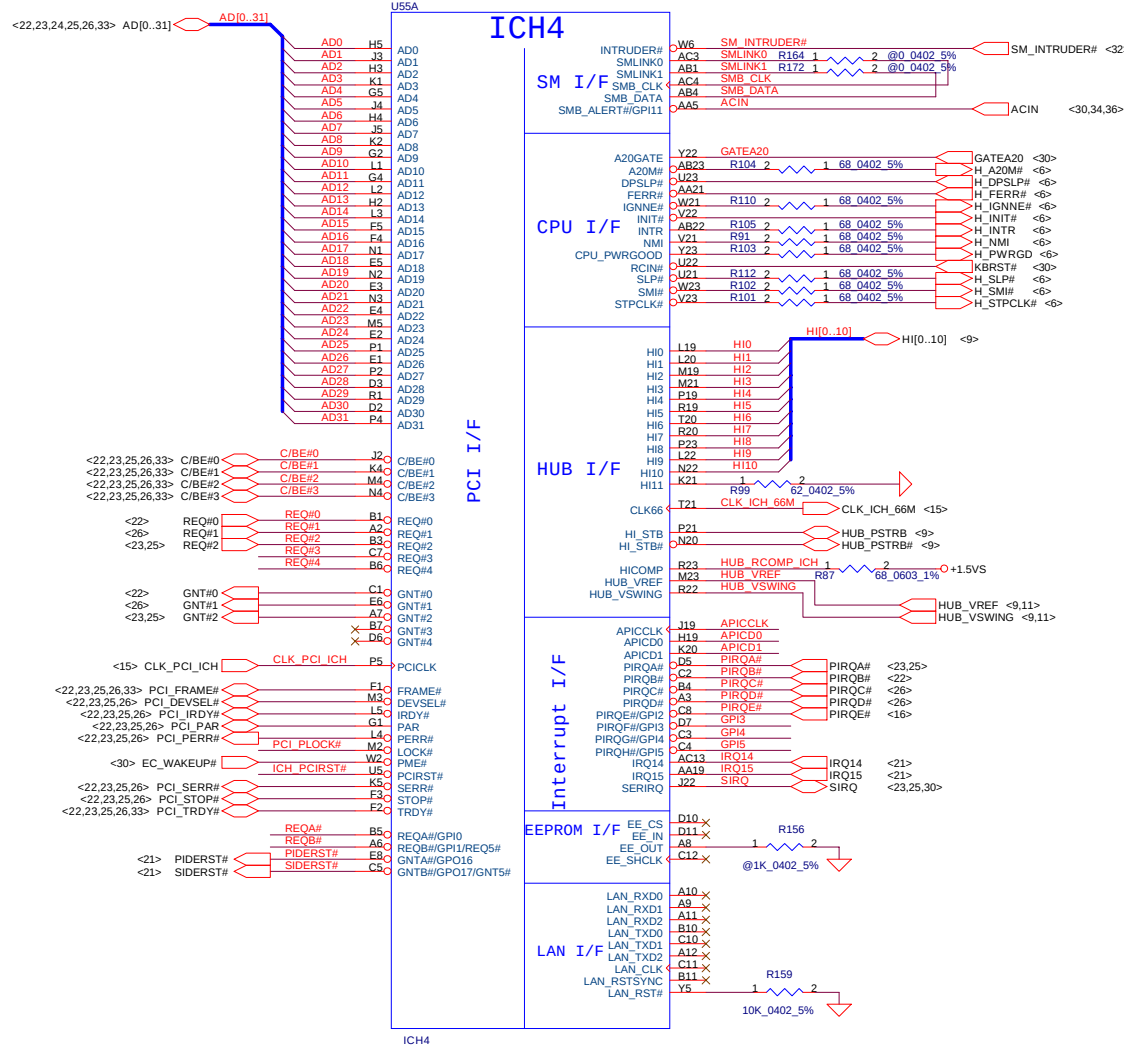
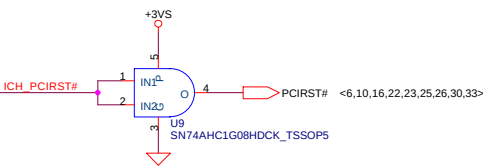
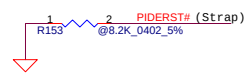
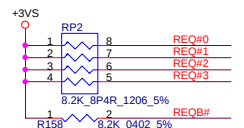
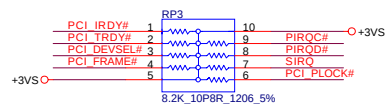
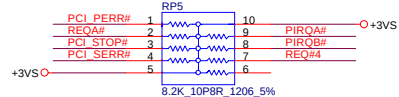
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Title			
TVOUT & CRT			
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Date:	Tuesday, November 26, 2002	Sheet	17 of 46

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PCI Pullups



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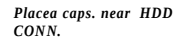
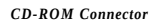
Compal Electronics, Inc.

INTEL ICH4(1/3)

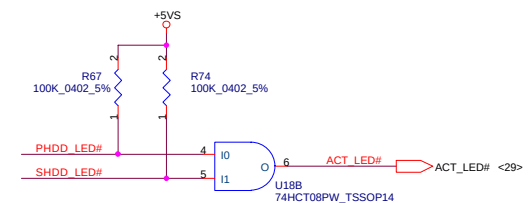
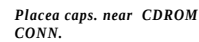
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Date:	Tuesday, November 26, 2002	Sheet 18 of 46

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Correct HDD pin define ,pls update layout

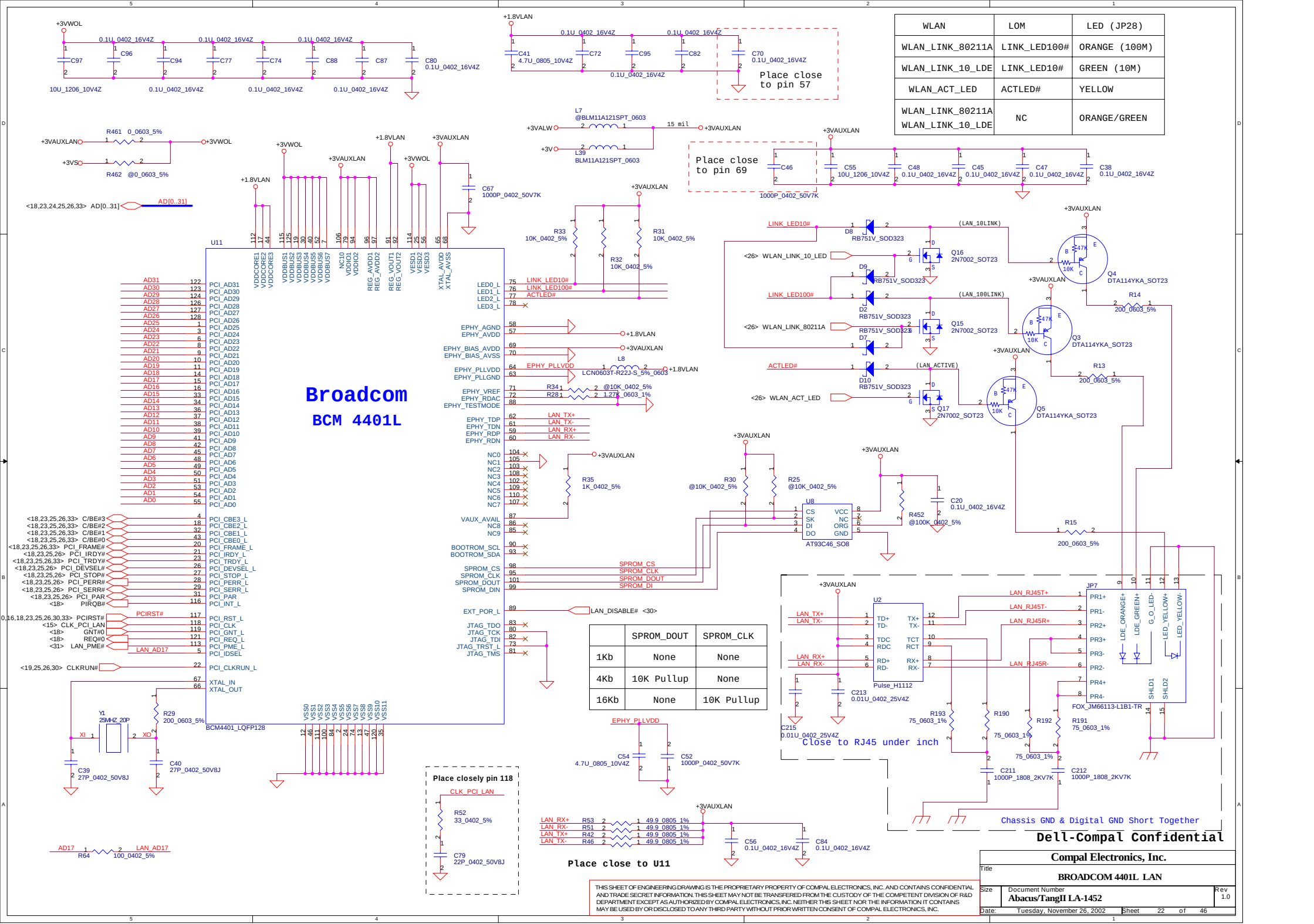


Layout Note: +5VSHDD trace
width 60 mil

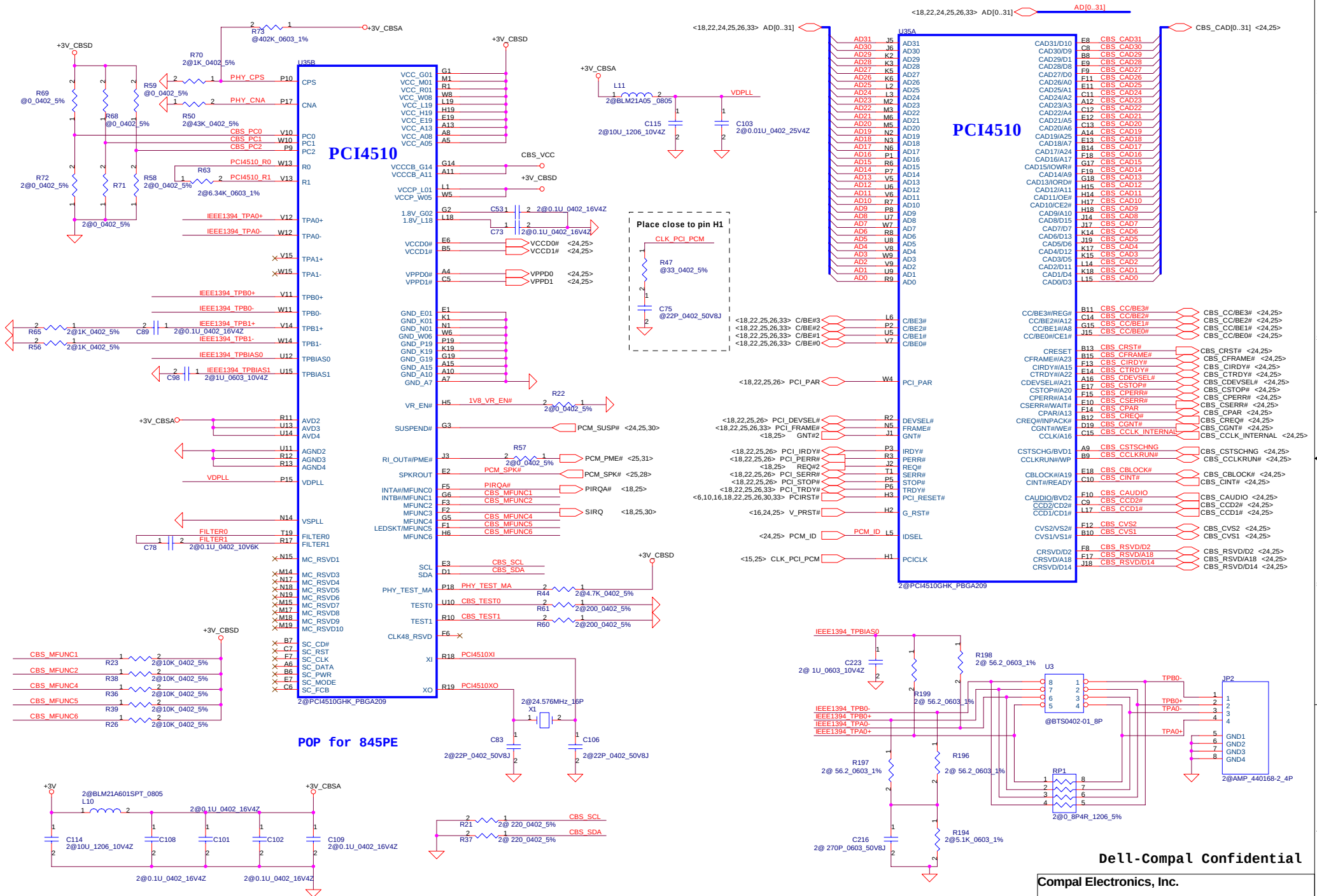


Title			
IDE/FDD/CD-ROM Module			
Size	Document Number	Rev	
	Abacus/TangII LA-1452	1.0	
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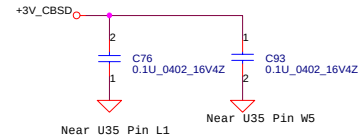
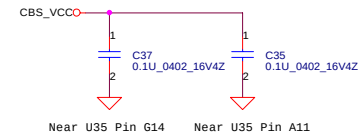
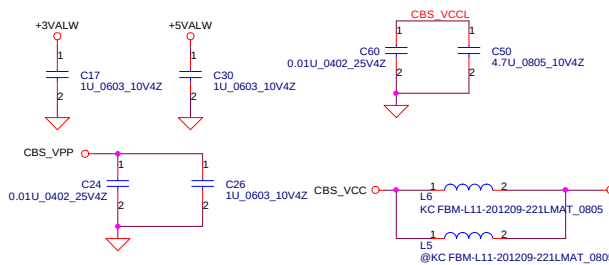
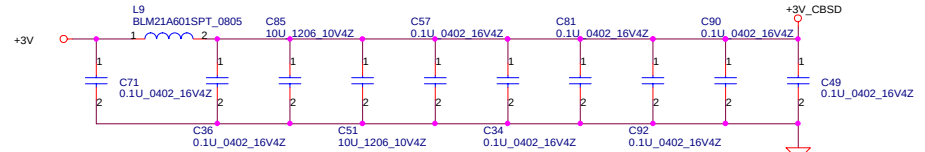
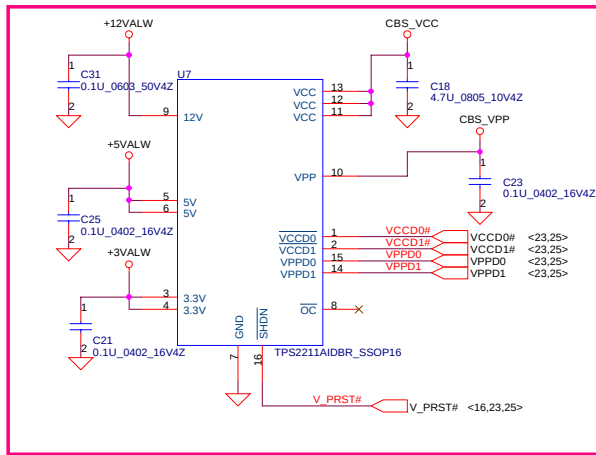
Compal Electronics, Inc.

Title	PCMCIA & 1394 Controller PCI4510
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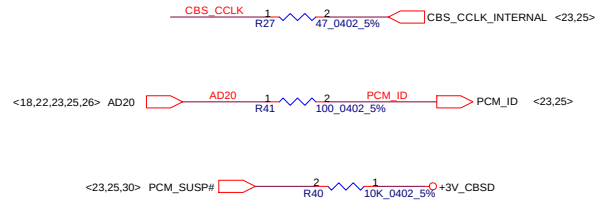
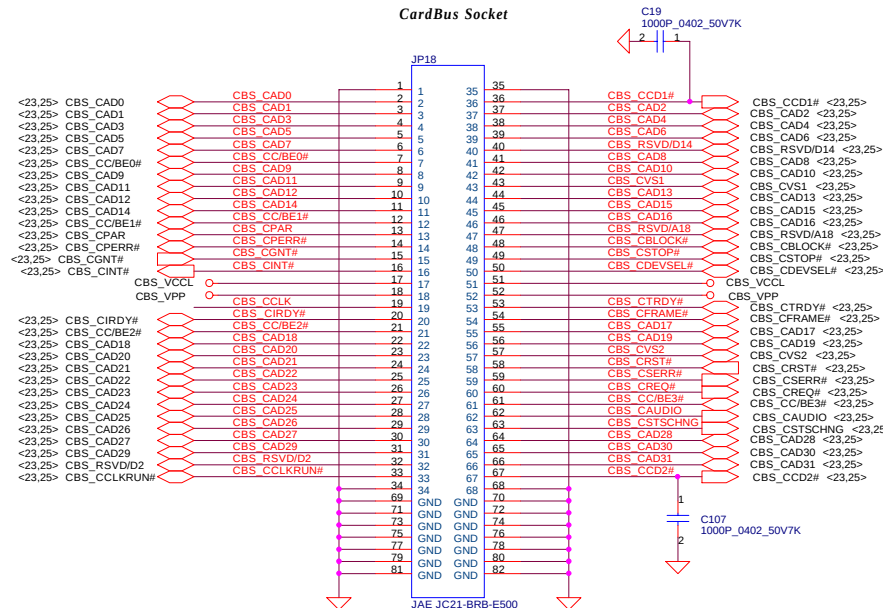
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	Abacus/TangII LA-1452			
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PCMCIA Power Controller



CardBus Socket



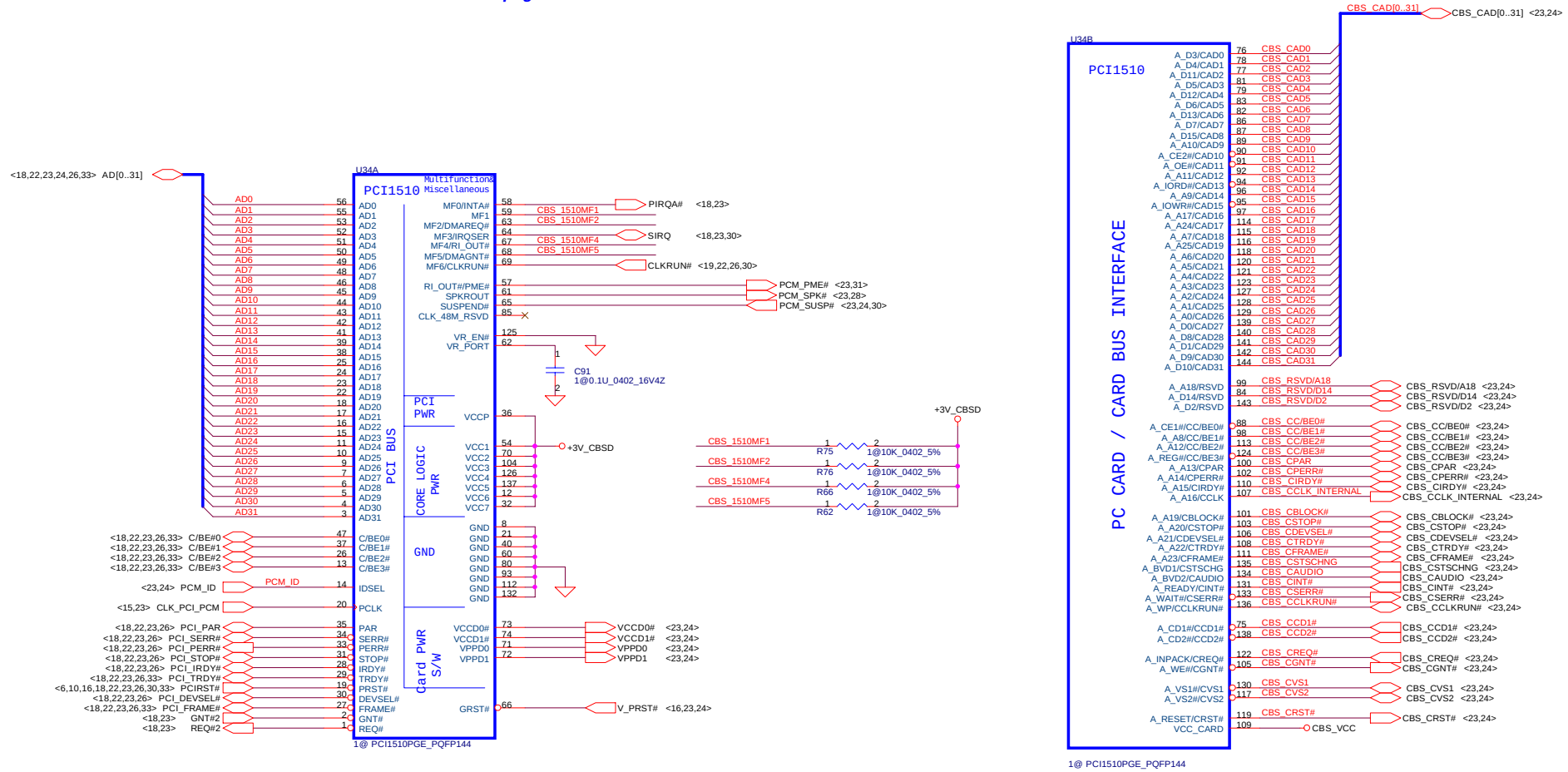
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Title			PCMCIA Socket
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1@ PCI1510PGE_PQFP144

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Compal Electronics, Inc.

Title
PCMCIA Controller PCI1510

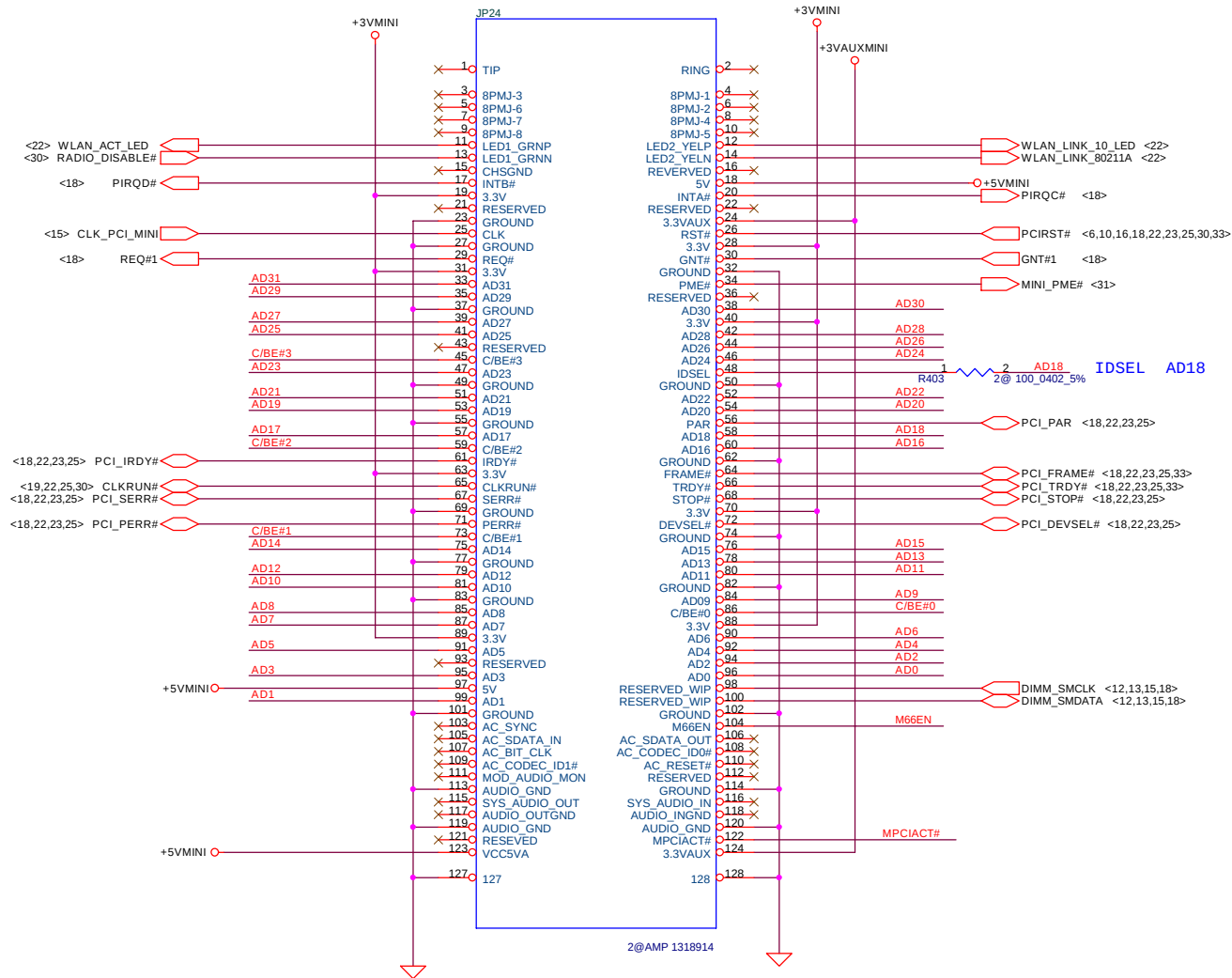
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Document Number
Abacus/Tangil LA-1452

Rev
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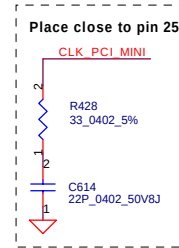
Date: Tuesday, November 26, 2002 Sheet 25 of 46

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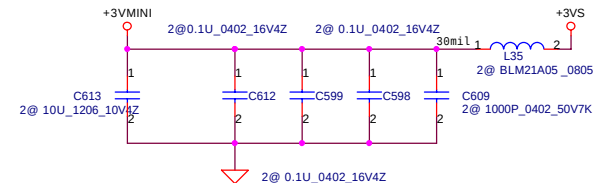
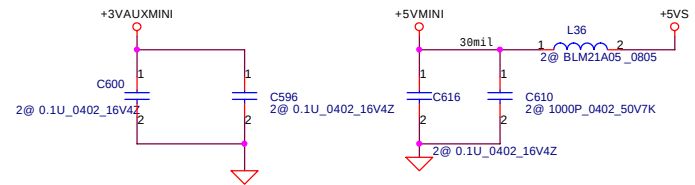
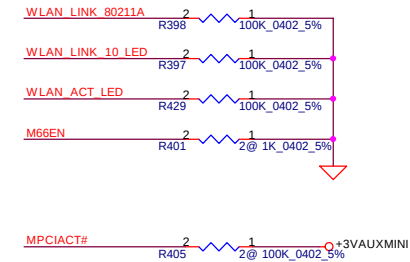
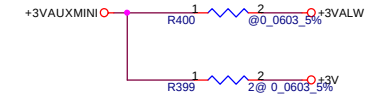
MINI PCI TYPE III



WIRELESS SUPPORT ONLY



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<18,22,23,25,33> C/BE#[0..3]

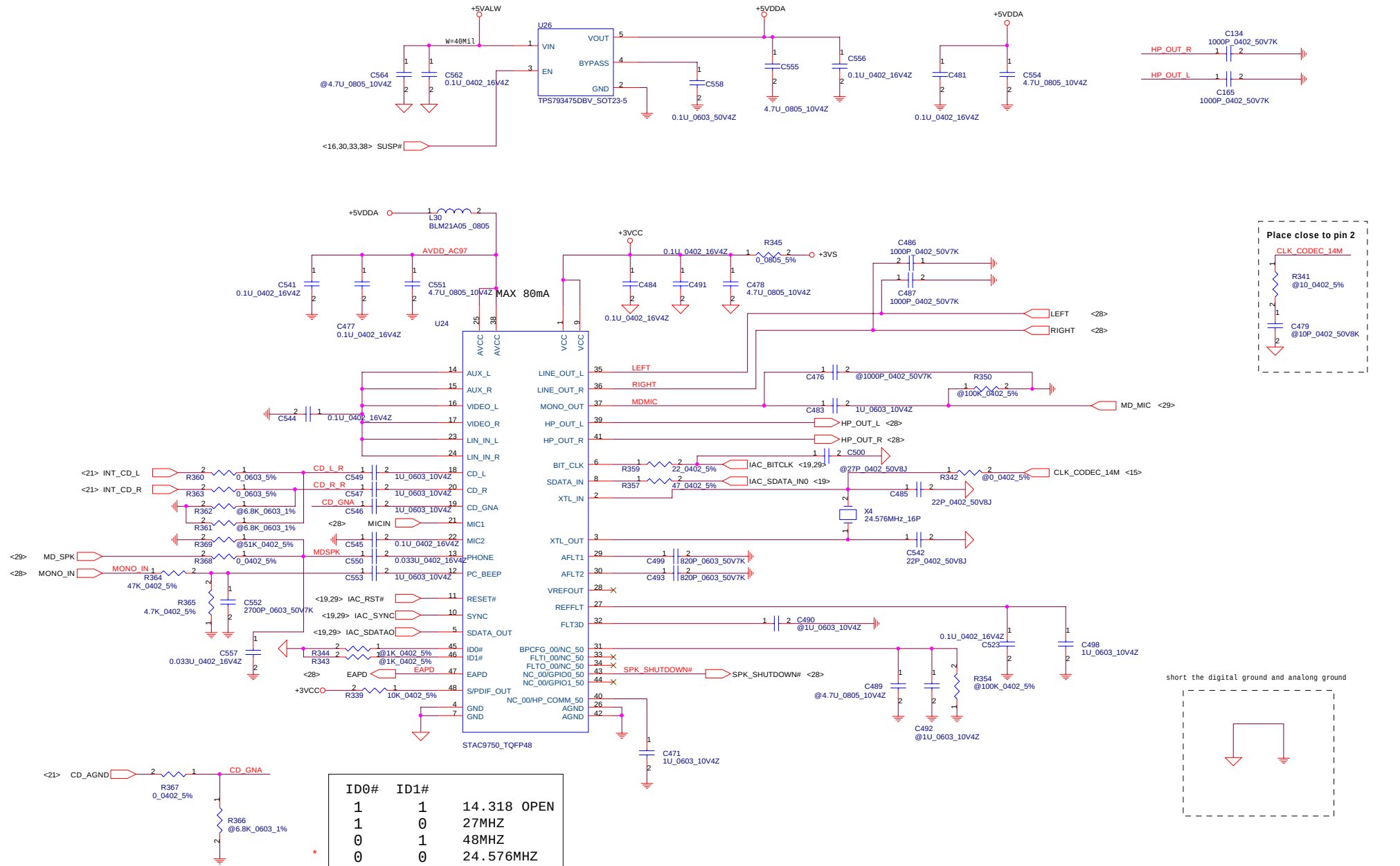


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Title			
MiniPci Port			
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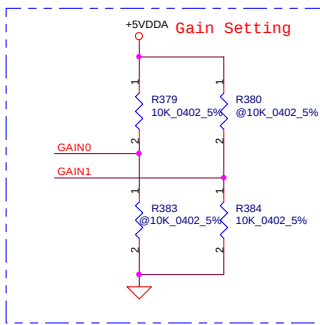
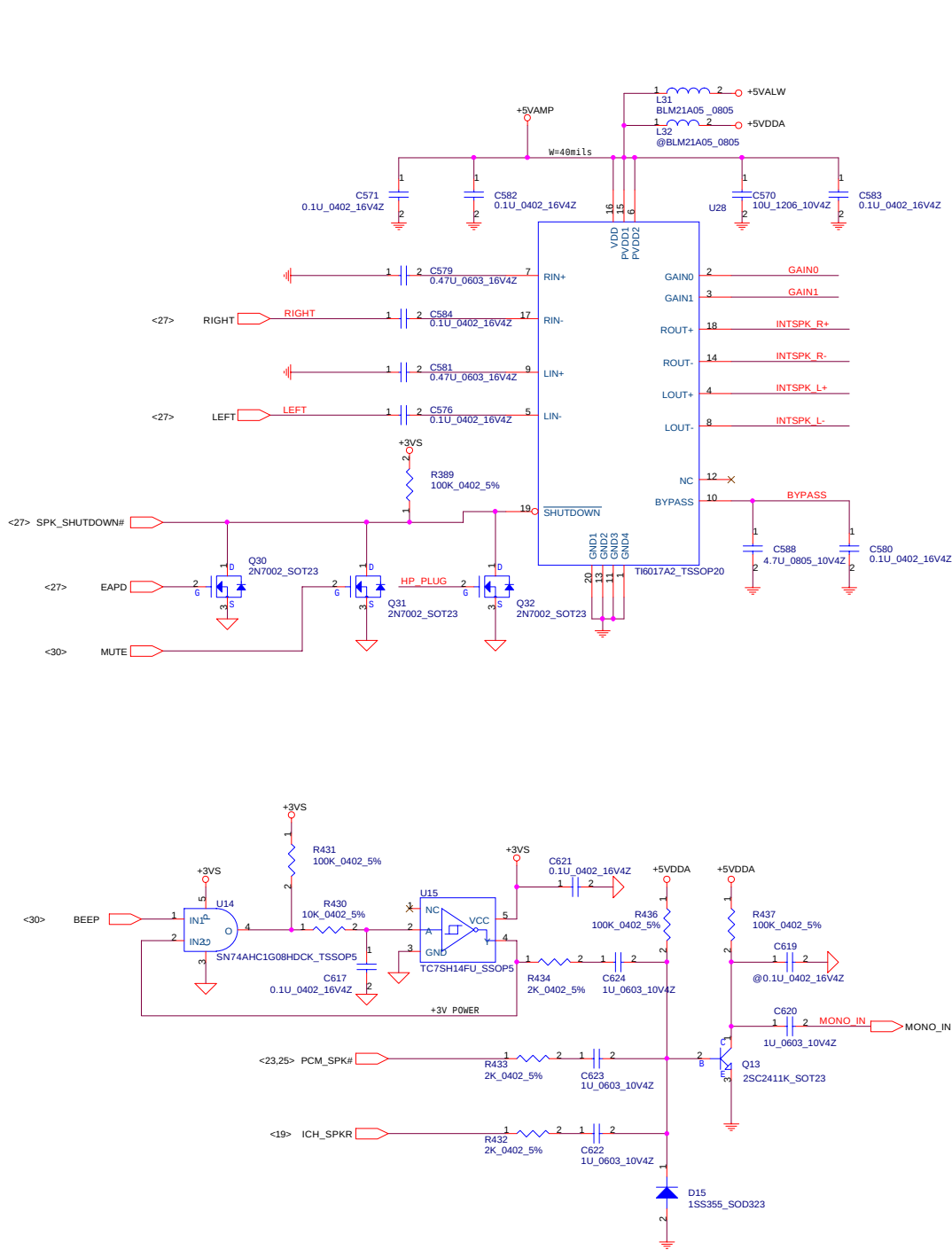


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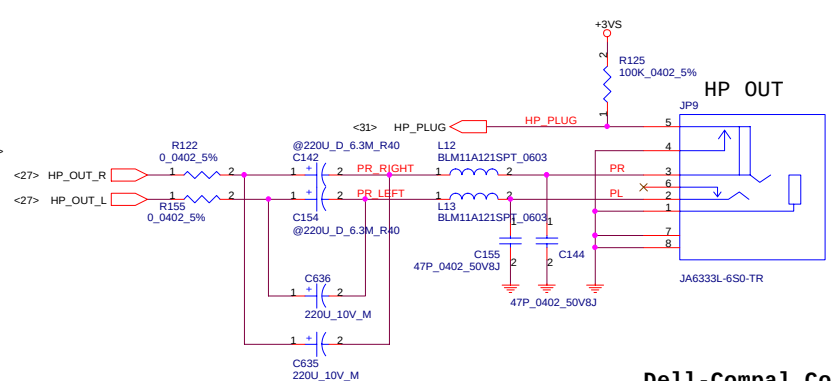
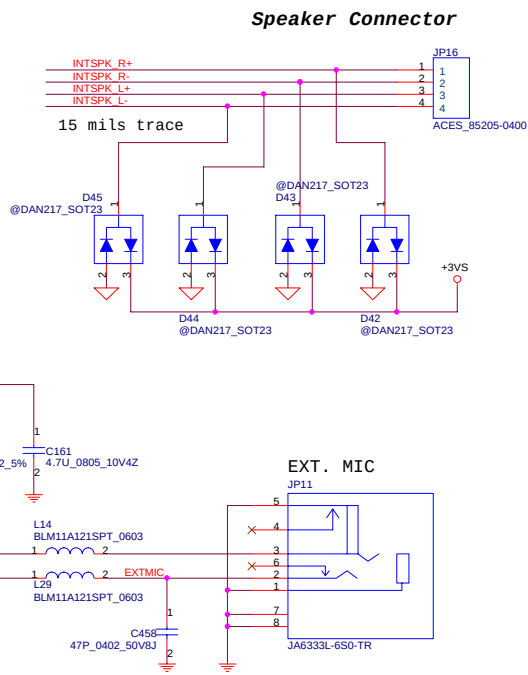
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Title			
AC97 CODEC			
Size	Document Number	Rev	
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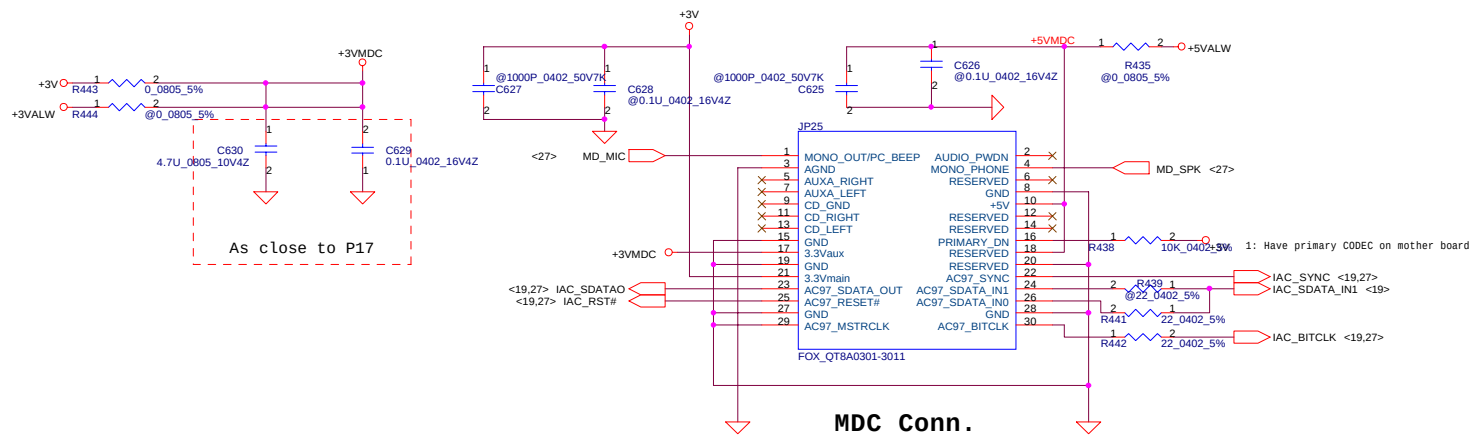
GAIN0	GAIN1	AV(inv)	INPUT IMPEDANCE
0	0	6dB	90K ohm
0	1	10dB	70K ohm
1	0	15.6dB	45K ohm
1	1	21.6dB	25K ohm



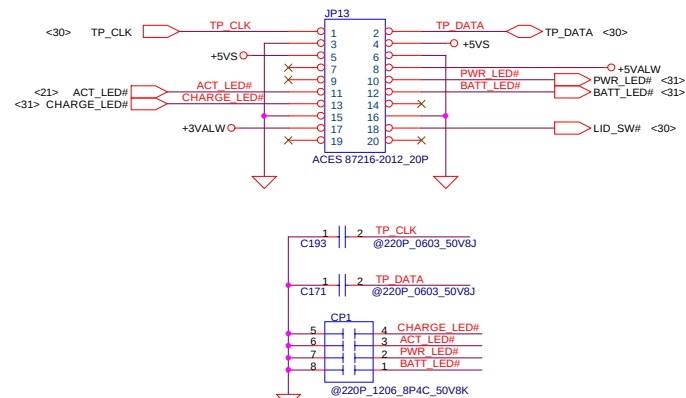
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Title			
AMP & Audio Jack			
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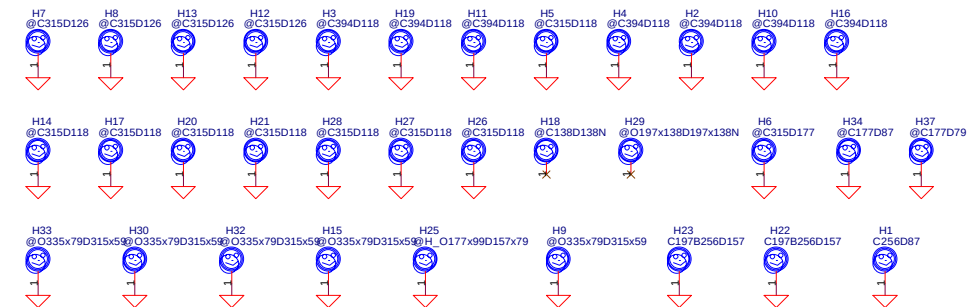
Touch Pad & Status LED Conn.



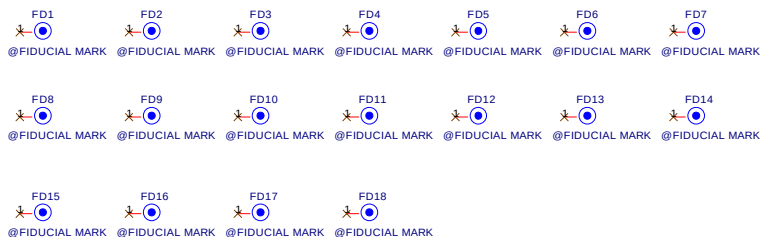
MDC Note

Pin 1 is NC for Pctel and connexant MDC modem
Pin 2 is NC for Pctel and connexant MDC modem

Screw Hole



Fiducial Mark

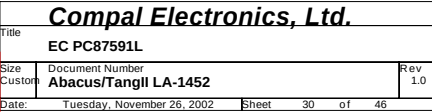


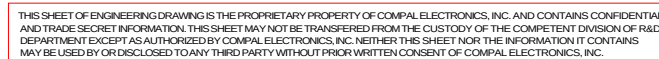
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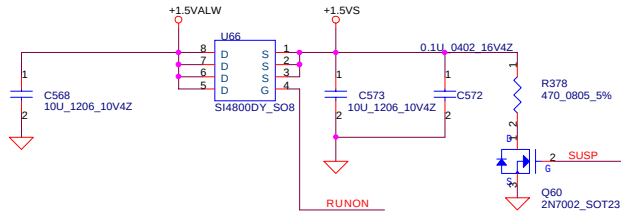
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MDC / SWITCH Connector		
Size	Document Number	Rev
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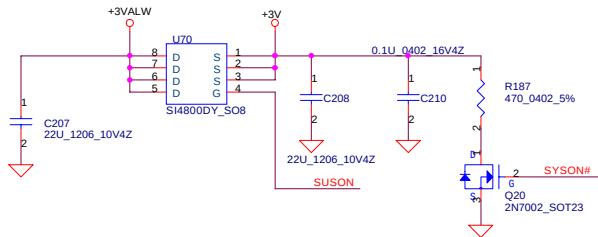




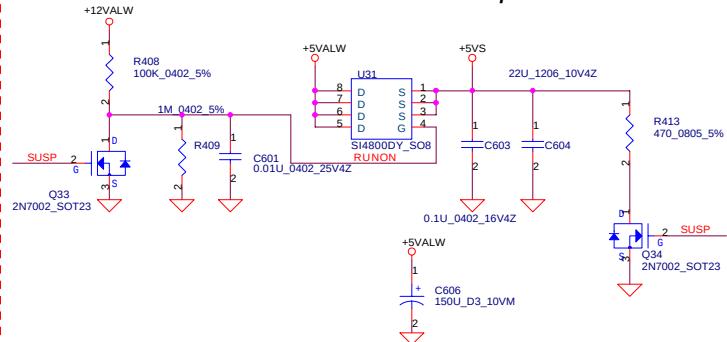
+1.5VALW to +1.5VS Transfer



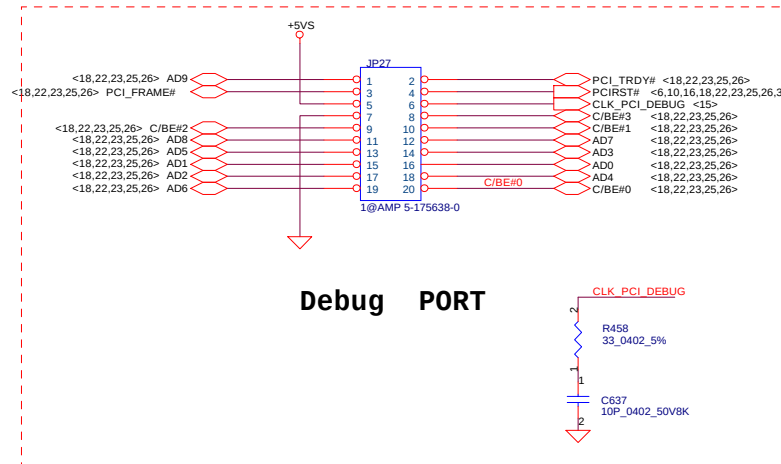
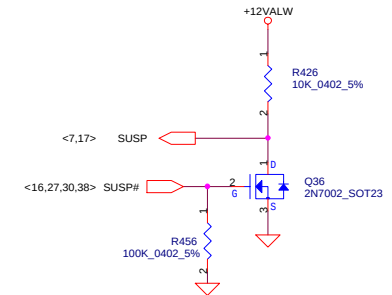
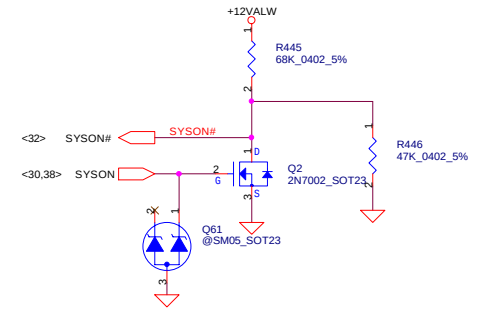
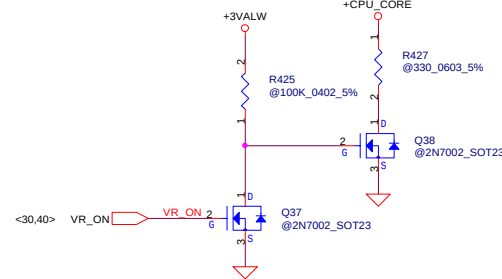
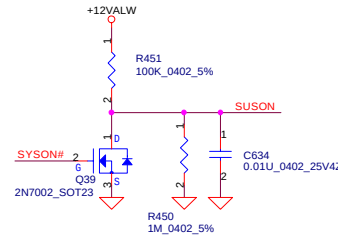
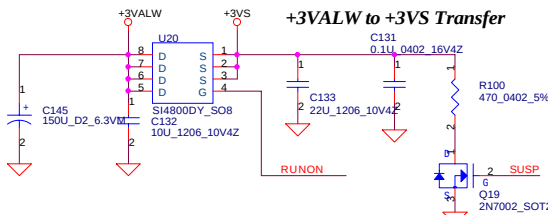
+3VALW to +3V Transfer



+5VALW to +5VS Transfer



+3VALW to +3VS Transfer



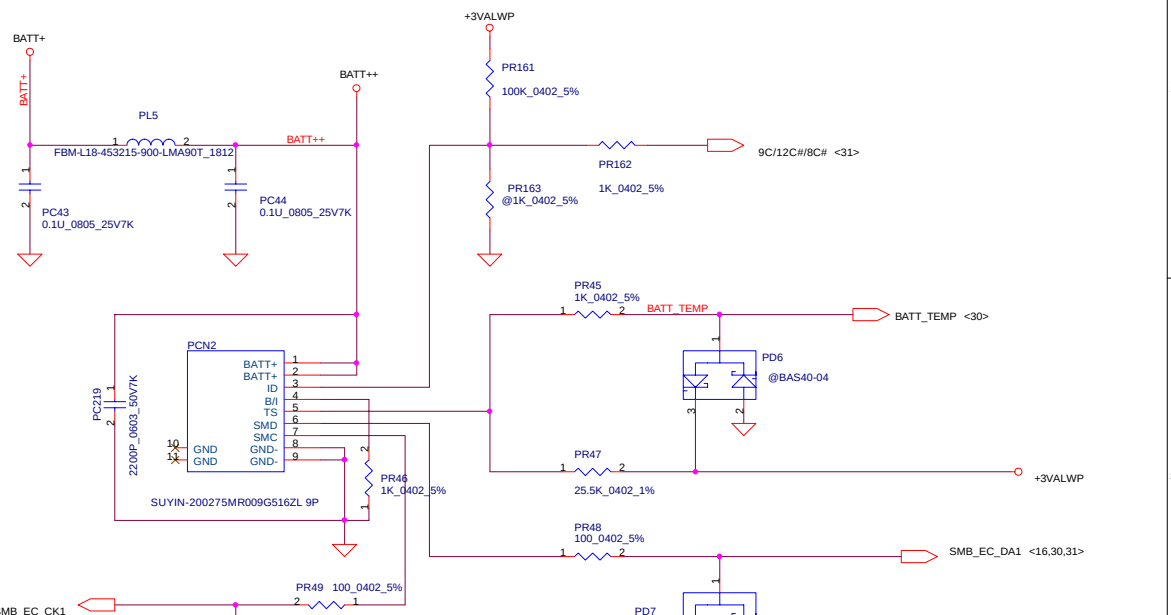
Debug PORT

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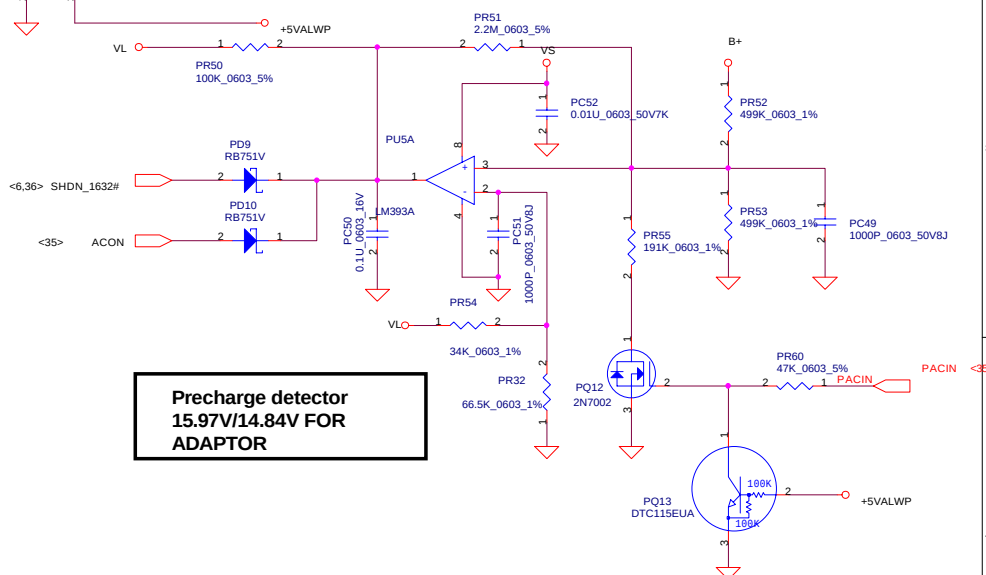
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DC/DC Circuit / Debug Port			
Size	Document Number	Rev	
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SMART Battery:
1.BATT+
2.BATT+
3.9C/12C#/8C#
4.B/I
5.TS
6.SMB_EC_DA1
7.SMB_EC_CK1
8.GND
9.GND

The schematic diagram illustrates the input stage of the ADXL345, centered around the LM393A op-amp. The op-amp is configured with its non-inverting input (pin 5) connected to the VS pin and its inverting input (pin 6) connected to the ACIN pin. The output (pin 7) is connected to the PACIN pin. The op-amp is powered by a 1.6V supply (pin 4) and has its ground (pin 8) connected to the RTCVREF pin. The op-amp is also connected to the VS pin via a 10K resistor (PR56). The input stage includes several external components: a 1000pF capacitor (PC53) connected to the VS pin, a 22K resistor (PR61) connected to the VS pin, a 10K resistor (PR64) connected to the RTCVREF pin, a 10K resistor (PR59) connected to the ACIN pin, a 10K resistor (PR63) connected to the PACIN pin, a 10K resistor (PR58) connected to the VS pin, a 10K resistor (PR57) connected to the VS pin, a 10K resistor (PR62) connected to the VS pin, and a 10K resistor (PR55) connected to the VS pin. The op-amp is also connected to the VS pin via a 10K resistor (PR56).



**Precharge detector
15.97V/14.84V FOR
ADAPTOR**

I_{adp}=0~4.10A(90W)
I_{adp}=0~3.20A(70W)
I_{air}=0~2.25A(Air)

I_{REF}=0.82*I_{charge}
I_{REF}=0~3.3V

Charge voltage
4S CC-CV MODE : 16.8V
V_{CHG} is H
4S PULSE MODE : 17.4V
V_{CHG} is L

OVP voltage :

LI-4S :18.0V----BATT-OVP=2.00V

LI-3S :13.5V----BATT-OVP=1.50V

BATT-OVP=0.2206*BATT++

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Charger

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+3.3V Ipeak = 6.66A ~ 10A

+5V Ipeak = 6.66A ~ 10A

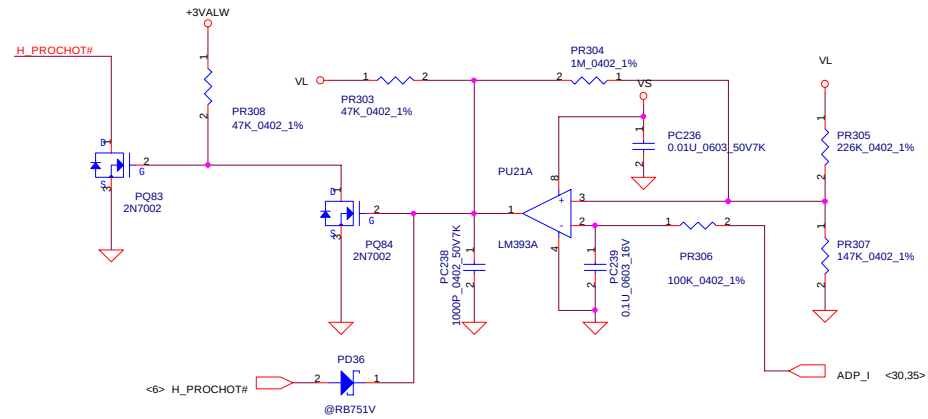
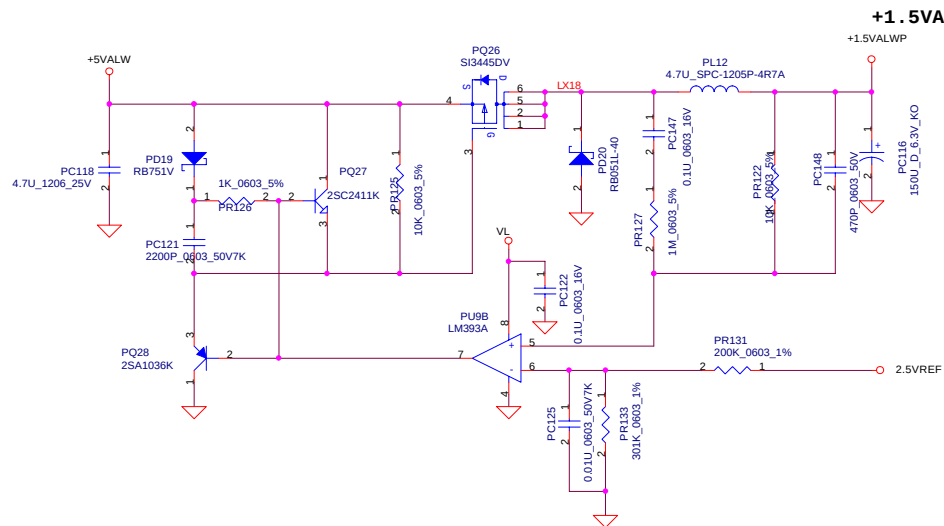
CPU thermal protection at 87 degree C
Recovery at 45 degree C

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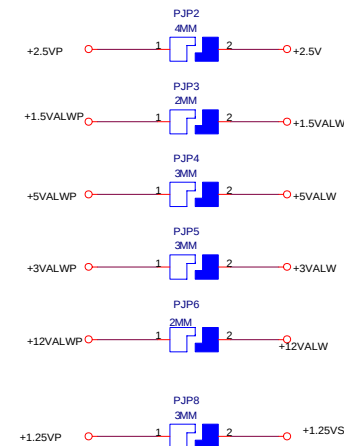
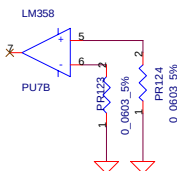
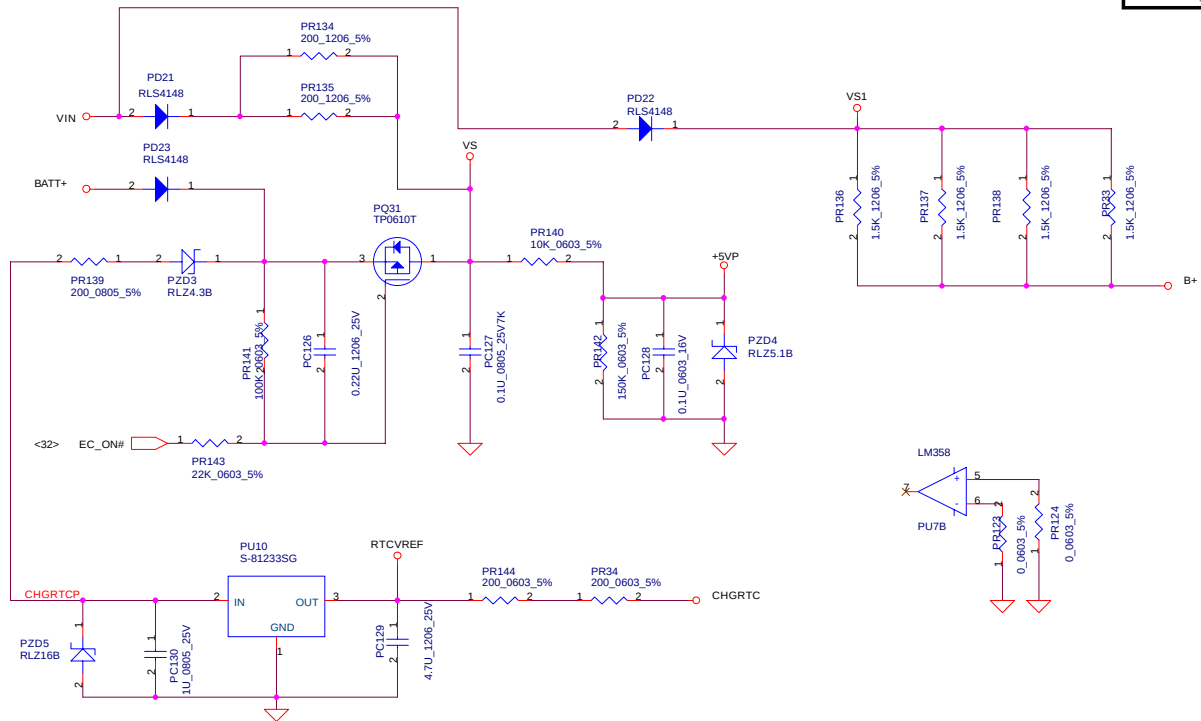
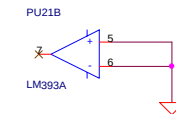
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Title			+3.3V/+5V/+12V	
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Adaptor Current Detector
ADP_I : 2.2V.... clock throttle(lin=5.5A)
ADP_I : 1.8V....No clock throttle(lin=4.5A)



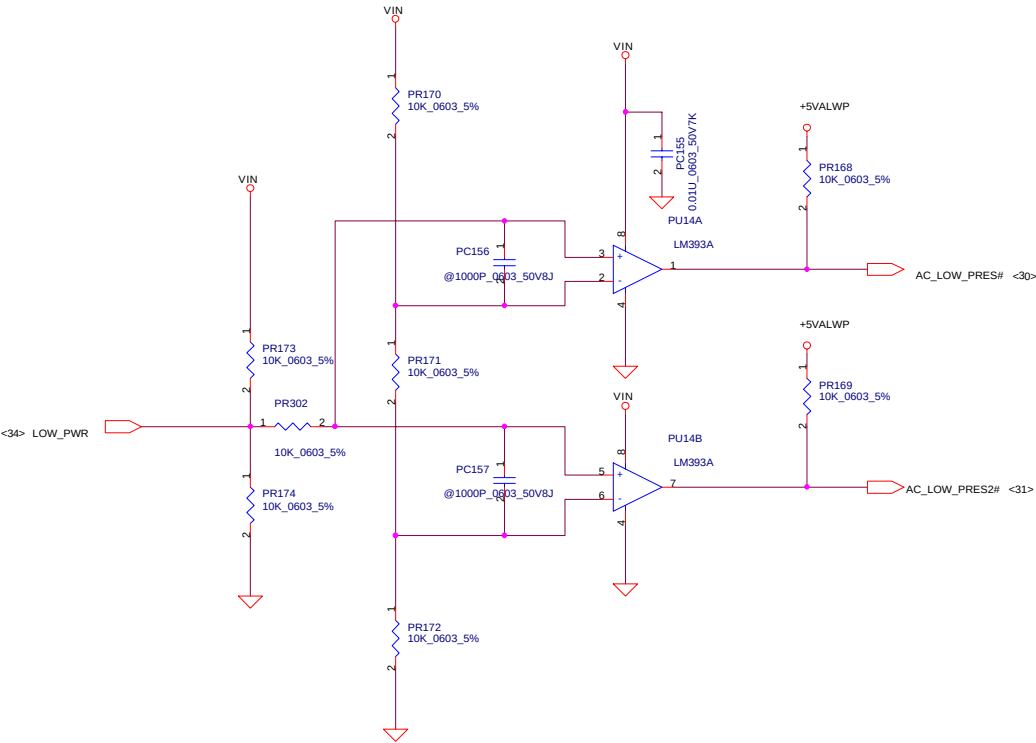
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Title		
+1.5VS		
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AC Adapter Detector



AC Adapter	LOW_PWR	AC_LOW_PRES#	AC_LOW_PRES2#	IREF2
90W	0V	0	0	2.96V
70W	Float	0	1	2.31V
AIRLINE	20V	1	1	1.62V

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Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	B.Ver #	Phase
1	Fireware issue	The ICH4 GN1A# strap pull up for EC BIOS	0.1A	18	Depop R153, GN1A# have internal pull up	0.1	SST
2	Leakage current issue	Reduce Broadcom 4401L leakage current	0.1A	22	Depop L39 and pop L7, connector power source from +3VALW to +3V, R31, R32, R33 pull up to +3VAUXLAN, Q3,Q4,Q5 pin3 connect to +3VAUXLAN	0.1	SST
3	Fix schematics part value	L21, L22, L23, L26 part value different with BOM	0.1B	15	Change L21, L22, L23, L26 part value from CH62012U121 to BLM21A601SPT on schematics	0.1	SST
4	BOM issue	R445 include wrong part number	0.1B	33	Change R445 part number from S028470200 to S028680200. PN indicate value from 47K_0402_5% to 68K_0402_5%	0.1	SST
5	HDD leakage current issue	When AC in +5VSHDD will go up to 5V	0.1C	21	Q6 change to SI2302DS as schematics, SI0EPWR active low when HDD power on	0.1	SST
6	Capture library package issue	2N7002 Drain is pin1, Source is pin3	0.1C	28	Fixed Q30, Q31, Q32 Capture library, pin1 fixed to pin3, pin3 fixed to pin1	0.1	SST
7	BOM issue	Fixed R196-R199 from 56.2K ohm to 56.2 ohm	0.1C	23	Change R196-R199 PN from S0014562207 to S0014562A00 on schematics	0.1	SST
8	Fix LOM EEPROM issue	U8 (AT93C46) is used X16 organization	0.1C	22	NC or pop R452 to pull up U8 pin6 for X16 organization select	0.1	SST
9	Fix CLKRUN# leakage issue	ICH4 not implement CLKRUN#, GPIO24 is resume power well.	0.1D	19	Add a diode D46 to isolate GPIO24 from ICH4 to PCI devices, and depop D46.	0.2	PT
10	LOM EEPROM issue	U8 (AT93C46) is used X16 organization. U8 pin6 pull up or NC for X16 organization select, pull down for X8 organization select.	0.1D	22	U8 pin6 pull up +3VAUXLAN via R452, and depop R452.	0.2	PT
11	SW BD LED keep turn on	SW BD LED control transistor Emitter connect to +5VALW be keep LED always turn on	0.1D	32	Change JP5 pin9 from +5VS to +3VS	0.2	PT
12	Fix VCCA_SM voltage drop issue	Add current rating for VCCA_SM, VCCA_DPLL, VCCA_FSB (1.5VS)	0.1E	10	Change L3, L4, L27, L28 from MLF2012DR68XT to FBM-L11-201209-121LMA05	0.2	PT
13	Change address and control signals layout topology	Change ddr address and control signal layout topology	0.1E	12,13	D0R address and control signals layout topology same the ddr data layout topology	0.2	PT
14	Fix EE issue item 89	Signal COMP/B and Y/G connect error	0.1E	17	Swap COMP/B and Y/G to correct connection	0.2	PT
15	Fix EE issue item 91	BEEP# from EC should be high active	0.1E	28	Change net name BEEP# to BEEP	0.2	PT
16	Fix EE issue item 92	Fix FSB 400MHz when 8456L pop	0.1E	15	Add R455 (8.2K_5%) pull down for H_BSEL0	0.2	PT
17	Fix EE issue item 95	When AC insertion SUSP# may be floating before the KBC can programit.	0.1E	33	Add R456 (100K_5%) pull down SUSP#	0.2	PT
18	Fix EE issue item 47	Provide enough current rating	0.1F	15	L22 and L26 change from BLM21A601SPT (300mA) to FBM-L11-201209-121LMA05 (500mA) and depop L22	0.2	PT
19	Card Bus power bead current rating not enough	Provide enough current rating	0.1F	24	L5 and L6 change from FBM-L1-160808-800LMT-0603 (300mA) to FBM-L11-201209-121LMA05 (500mA)	0.2	PT
20	Fix EE issue item 102	Fix Intel CPU FSB frequency issue	0.1F	10,15	H_SEL0 connect to R270 pin1 from CLK generator, H8SEL0 connector to R270 pin2 from CPU. Depop R270 on GL board.	0.2	PT
21	Battery charge issue	ACIN pull up +3VALW can't change power supplier to battery when AC exit	0.1F	18	Depop R161	0.2	PT
22	NO	Change PCMCIA connector	0.1F	24	Change PCMCIA connector from AMP_0-1376275-1 to JAE_JC21-BRB	0.2	PT
23	Fix INTRUDER issue	ESD protect for Q22	0.1F	32	Add C638, C639 for Q22 protection	0.2	PT
24	Remove PS2 connector	No necessary	0.1G	29	Remove RP7, JP26	0.2	PT
25	Add debug port	GL board have not pop minipci connector, we need a port 80 debug tool	0.1G	33	Add R458, C637 and JP27	0.2	PT
27	For cost save	For cost save	0.1G	32	Depop C10, C229 (150U Poly Cap), add C641, C642 (100U Petit Cap)	0.2	PT
28	It no need	Use R19 pop and depop to control H_SEL0 high or low	0.1G	15	Remove R455	0.2	PT
29	Fix EE issue item 134	Change ddr address and control signal layout topology	0.1H	12,13	Change D0R address and control signal to go back SST topology	0.2	PT
30	Fix EE issue item 149	Pop Petit Cap after EA test	0.1H	32	Depop C641, C642 and pop C10, C229	0.2	PT
31	Fix EMI issue	EMI team's recommendation	0.1I	10	Pop R52, C79 for CLK_CLK_PCI_LAN; R428, C614 for CLK_PCI_MINI; R406, C597 for CLK_PCI_LPC; R321, C395 for CLK_ICH_66M	0.2	PT

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Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	B.Ver #	Phase
32	No	Connect MiniPci connector metal door to short to GND	0.1I	26	Add JP24 pin 127, 128 on schematics short to GND, JP24 footprint pin 127, 128 (metal lock door) be short to GND	0.2	PT
33	No	Some text mode use wire, change to line	0.1I	10,30,40	Some text mode use wire, change to line	0.2	PT
34	Fix power on issue	Use PCIRST# to set the SHDN_1632# work after PCIRST# high when power on	0.1I	6	Add Q62 gate connect to PCIRST#, source connect to SHDN_1632#	0.2	PT
35	No	Change to use approve part	0.1I	31	RP18 (8.2K +-5% 4P2R) change to R453, R454 (8.2K-0402-5%)	0.2	PT
36	No	Hard Disk source power change to +5VS	0.1I	21	Q6 change back to SI2301DS (PMOS) pin3 connect to +5VS	0.2	PT
37	Fix EE issue item 134	Change DDR address and control signal topology back to REV0.1	0.1I	12,13	Change DDR address and control signal topology back to REV0.1	0.2	PT
38	Fix EE issue item 171	For CRT Hsync and Vsync to allow tuning	0.1I	17	Add series resistors R459, R460 for Hsync and Vsync	0.2	PT
39	No	Schematic version change for PT build	0.2	ALL	Change revision from 0.1I to 0.2	0.2	PT
40	Fix issue item 20	Slow rising and falling time	0.2A	10	Pop R234, C249 for CLK_MCH_DISPLAY; R286, C333 for CLK_MCH_66M	0.2	PT
41	Fix CRT rising and falling time issue	Fast rising and falling time	0.2A	17	Pop L1, L2, L15 Change form FCM-2012C-800 to FBM-10-201209-260T for PE board	0.2	PT
42	No	Change Board ID output level	0.2A	30	Pop R393 100K-0603-1% for Board ID	0.2	PT
43	No	Add off-page reference	0.2A	24	Add off-page on pg24 PCMCIA connector	0.2	PT
44	No	Net in for Rev 0.2A Gerber	0.2B	ALL	Modify Text	0.2A	PT-2
45	Fix DFX issue	C387 effect DIMM door lock	0.2C	21	Add C643 22U-1206 replace C387's layout location and C387 leave DIMM area.	0.2A	PT-2
46	No	Add JP18 PCMCIA connector GND pads	0.2C	24	JP18 pin75,76,77,78,79,80,81,82 connect to GND	0.2A	PT-2
47	No	PM_GMUXSEL for mobil platform to support SpeedStep, desktop platform just GPIO fuction	0.2C	19	Remove PM_GMUXSEL signal net	0.2A	PT-2
48	Fix PIR2 issue	PIR not match schemaitcs	0.2F	22	Pop L39 and depop L7	0.2A	PT-2
49	Fix PIR19 issue	PIR not match schemaitcs	0.2F	24	C5, L6 change to FBM-L11-201209-221LMAT (3A). And Depop L5	0.2A	PT-2
50	Fix PIR23 issue	PIR not match schemaitcs	0.2F	32	Depop C638	0.2A	PT-2
51	Fix PIR24 issue	PIR not match schemaitcs	0.2F	30	RP7 pop for pull up PS2 signal	0.2A	PT-2
52	Fix PIR25 issue	PIR not match schemaitcs	0.2F	33	JP27 pop on GL board for debug and depop on PE board	0.2A	PT-2
53	Fix EE issue item 62	Schematics component's PN not match BOM	0.2G	29	JP13 (TP CONN) PN change to "SP020010910" in schematics to match BOM	0.2A	PT-2
54	Fix EE issue item 63	Schematics component's PN not match BOM	0.2G	29	JP25 (MDC CONN) PN change to "SP02F00410L" in schematics to match BOM	0.2A	PT-2
55	Fix EE issue item 64	Schematics component's PN not match BOM	0.2G	32	JP4 (USB CONN) PN change to "0C23310241L" in schematics to match BOM	0.2A	PT-2
56	3VDDCbA, 3VDDCCr rising time issue	3VDDCbA, 3VDDCCr rising slow on SMBus EA measurement	0.2G	17	R5, R201 change from 10K-0402-5% to 2K-0402-5%	0.3	ST
57	EE issue list item 91	CLK_PCI_ICH timing out of spec	0.2H	18	Pop R349 (22-0402-5%), C400 (10P-0402-50V8K) for CLK_PCI_ICH AC termination	0.3	ST
58	EE issue list item 103	Depop sub thermal sensors for cost save	0.2H	8	Depop U25, U23, C394, C482, R308, R351 and R306	0.3	ST
59	Fix Boardcom 4401L wake up from S3 issue	Fix Boardcom 4401L wake up from S3 issue	0.2H	22	Add R461, R462 and depop R462. Option VESD and VDDBUS power source from +3VS to +3VAUXLAN. C97, C96, C77, C74, C88, C87, C80 bypass +3VWOL	0.3	ST
60	EE issue list item 103	H_BSEL0 of 845PE should get 1.5V at input and CLK chip should be seeing 3.3V with 533MHz CPU	0.2H	15	Add R463 (0-0402-5%) Pop on PE board. R19 move to CPU side and power source +3VS.	0.3	ST

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Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	B.Ver #	Phase
61	ESD protection on 2nd FAN	ESD protection on 2nd FAN	0.2I	7	Reserve Q63 (SM05) for 2nd FAN ESD protection	0.3	ST
62	Fix EE issue item 105	H_BSEL0 circuit not correct	0.2I	10, 15	Serie resistor R270 for CPU and MCH	0.3	ST
63	No	Change Board ID for ST build	0.2I	30	R394 change from 10K_0603_1% to 24.9K_0603_1%	0.3	ST
64	No	Change for ITP test on PCBA	0.2I	6, 8	Depop R313, R305 and pop R310, R372, R183, R184, R304	0.3	ST
65	Fix EE issue item 126	Using larger cap for high-pot margin	0.2J	22	C211, C212 change package from 1206 size to 1808.	0.3	ST
66	RJ11 ISN failed	EMI team recommend to resolve RJ11 ISN test failed	0.2J	29	Cut a seperated GND for MDC and connect to system GND via a schottky diode. Reserve a jump for connect system and MDC GND.	0.3	ST
67	Fix EE issue item 140	Connect 9C/12C#/8C# to EC GPIO for future 9Cell support if required	0.2K	31, 34	Connect 9C/12C#/8C# from PR162 to U30 pin17 and remove R388	0.3	ST
68	TI TPS793475DBVR damage issue	When power on, there are 1.5A sink current when TPS793475DBVR started	0.2K	29	For power solution, C558 change package size from 0402 to 0603 for value tolerance	0.3	ST
69	Fix EE issue item 136	Add hardware circuit to sense Adapter current and automatically generate PROCHOT to the CPU to generate automatic throttling	0.2K	6	R311 change to 4.7K_0402_5%, H_PROCHOT# connect to PD36	0.3	ST
70	Fix ThermTrip function	When thermal protective resistor PH1 work, SHDN_1632# can't tie to low	0.2K	6	R320 connect to Q59 base, R316 connect to Q59 collector and VL power source. Add Q64 between Q59 and Q62. Q62 change pin1 Drain to connect SHDN_1632#	0.3	ST
71	RJ11 ISN failed	Change solution for ISN failed	0.3	29	Remove PJP9-13 and D47	0.3	ST
72	Fix EE issue item 136	Follow Intel desing guide recommend pull up resistor value	0.3	6	R311 change back to 62_0402_5%	0.3	ST
73	Fix EE issue item 141	Prevent noise issue	0.3	28	Depop R328 for noise prevention	0.3	ST
74	No	For cost save	0.3	7	Depop C148, C150 (470U_D4_2.5VM) and C152 (330U_D2E_2.5VM)	0.3	ST
75	Fix PROTO3 EE issue item 44	Minipci connector pop for PE board only	0.3B	26	Add 2@ symbol for JP24 for PE board pop only	0.3	ST
76	No	Vendor schematics review recommendation	0.3B	22	R35 change from 10K_0402_5% to 1K_0402_5%	0.3	ST
77	Fix PROTO3 EE issue item 45	Remove minipci suport component for GL board cost save	0.3B	26	Remove R405, R399, C600, C596, C613, C612, C599, C598, C609, L35, C616, C610, L36, R401, R403 on GL board	0.3	ST
78	No	Modify material value	0.3C	23, 26, 27, 28	Change value L11, L30, L31, L35, L36 from BDM21A05_0805 to BLM21A05_0805	0.3	ST
79	No	Modify material part number	0.3C	27	U24 STAC9750 change from (SA097500000) to (SA097500010) for both BOM	0.3	ST
80	No	Depop Fan2 Control circuit	0.3C	7	Delete R11, D11, D20, U1, R10, R6, Q1, C234, Q8, JP19	0.3	ST
79	No	EMI require	1.0	17	Pop D1, D3, D18 for EMI requirement	1.0	QT
80	No	Modify Fiduiial Mark & Screw Hole value for non pop	1.0	29	Fiduiial Mark & Screw Hole value add @ symbol	1.0	QT

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Item	Fixed Issue	Reason for change	Rev.	PG #	Modify List	B.Ver #	Phase
1	CPU_CORE can't power up	Pin7 of PU16 can't be used as on/off control pin	0.1B	40	1. Change VCC power source of PU16 from +5VALWP to +5VS	0.1	SST
2	current limited is not up to 60A	Current limited is about 37A while PH6,PH7,PH8 is 1.5K that is not enough for design target.Because we don't use PTC resistor on PCB now, the value must be tuned later.	0.1B	40	1. Change PH6,PH7,PH8 from 1.5K_0603_5% to 3K_0603_1%	0.1	SST
3	Turn on voltage of PQ19 is not enough	Vgs of PQ19 is 2V while PR72 is 47K. That is not enough. While PR72 is 22K, the Vgs can be improved to 2.5V.	0.1B	35	1. Change PR72 from 47K_0402_5% to 22K_0402_5%	0.1	SST
4	current rating is not enough.	FBM-L11-322513-151LMAT is 5A that is not enough.So FBM-L18-453215-900LMA90T1812 is 9A that is better.	0.1B	35	1. Change PL8 from FBM-L11-322513-151LMAT to FBM-L18-453215-900LMA90T1812.	0.2	PT
5	Fix noise issue	On SST PCB, we can sound some noise due to PC77, the cernamic capacitor has sounded noise with thinner type.	0.1C	36	1. Change PC77 from 2.2U_1206_25V to 4.7U_1210_25V	0.2	PT
6	Fix CPU_CORE Transient Response fail	The transient response is too slow. We must to tune feedback resistor and capacitor to fix it.	0.1E	40	1. Change PR249 from 3.48K_0603_1% to 5.76K_0603_1%. 2. Change PR257 from 49.9_0603_1% to 1.1K_0603_1% 3. Populate PC172 68PF_0603_50V.	0.2	PT
7	SDREF output voltage is over spec.	Add bypass capacitor pallel pin18 of ISL6225	0.1E	38	Populate PC218 470P_0603_50V7K	0.2	PT
8	PG of CM28423 has a glitch while VCC is ready and VR_ON is float	Add pulldown resistor tie to GND while VR_ON is float that can be made sure the logic is low.	0.1E	40	Add PR301 100K_0603_1%	0.2	PT
9	Change VCC power source of PU15, PU17, PU19 from +5VALWP to +5VS	Negative voltage was observed on +5VALWP when system powered off	0.1E	40	1. Change VCC power source of PU15, PU17, PU19 from +5VALWP to +5VS	0.2	PT
10	Prevent abnormal function OVP caused by ISL6219 while system powerwd off ; bouble pulses was observed at output PW1, PW2, PWM3 of ISL6219	ISL6219 caused OVP when on/off pin changed from high to low level	0.1E	40	1. Add PQ82 2N7002 2. Change PR232 from 5.1_0603_5% to 10K_0603_5% 3. Change PC168 from 1U_0805_25V to 0.01U_0603_50V. 4. Depop PR251, PR270, PC183, PC194 5. Tie the EN pin of PU15, PU17, PU19 to Pin1 of PQ82	0.2	PT
11	Fine-tune current sharing of CPU VR phase1,2,3 to have thermal balance	uneven current sharing found	0.1E	40	1. Change PH6, PH7, PH8 form 3K_0603_1% to 0_0603_5% 2. Change PR245 from 0_0603_5% to 1.96K_0603_1% 3. Change PR263 from 0_0603_5% to 1.43K_0603_1%. 4. Change PR276 from 0_0603_5% to 1.5K_0603_1%	0.2	PT
12	Fine-tune CPU load-line with NTC	Fine-tune CPU load-line with NTC	0.1E	40	1. Keep PR268 nonpop 2. Change PR256 from 2K_0603_1% to 1.74K_0603_1% 3. Change PR297 from 0_0603_5% to 1.15K_0603_1%. 4. Change PH5from depop to 4.7K_0603_1% 5. Change PR298 from depop to 681_0603_1% 6. Change PR257 from 49.9_0603_1% to 909_0603_1% 7. Change PC179 from 3900P_0603_50V to 5.6N_0603_50V 8. Change PR249 from 3.48K_0603_5% to 7.5K_0603_1% 7. Change PC171 from 6800P_0603_50V to 5.6N_0603_50V 8. Change PC172 from depop to 47P_0603_50V	0.2	PT
13	Audio noise found	Still find root cause	0.1E	35, 36, 38, 40	1. reserve 15U_D_25V capacitors on PC226-PC235,	0.2	PT
14	PC212 location space change	requested by ME to put a connector around	0.1E	38	1. change the size of PC212 from D size to 0805 and pop 4.7U_0805_10V	0.2	PT
15	Remove PD5	no possibilty to have a reverse voltage at Vin when adapter plug-in because of the DC-jack orientation structure	0.2C	34	1.delete PD5 from schematics	0.2A	PT-2
16	Prevent PU14 from burn out	When pin1 (GND pin) of DC-jack PCN1 disconnected from B/M (damaged by force from outside), there is a large current going through PU14 resulted in PU14 damaged	0.2C	39	Add PR302 10K_0603_5%	0.2A	PT-2

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Version change list (P.I.R. List)

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Item	Fixed Issue	Reason for change	Rev.	PG #	Modify List	B.Ver #	Phase
17	100MHz EMI broad-band over spec.	Improve 100MHz EMI broad-band	0.2E	34	Add a FBM-L18-453215-900-LMA90T_1812 bead on PL7	0.2A	PT-2
18	100MHz EMI broad-band over spec.	Improve 100MHz EMI broad-band	0.2H	34	1. Change PL6,PL7 from FBM-L18-453215-900-LMA90T_1812 to MCK4532800YAT_1812 2. Add PL4 MBH2012102Yzt_0805 3. Change PC45 from 100P to 560P, PC46 from 1000P to 12P,PC47 from 100P to 12P and PC48 from 1000P to 560P	0.3	ST
19	Precharge function has some bug, while AC Adapter plug in first time	Precharge can reduce surge current from AC adapter,while Adapter plugged in	0.2H	34	1. Change PR51 from 1M to 2.2M,PR55 from 215K to 191K. 2. Change PR54 from 10K to 34K,add PR32 66.5K. 3. Change PC51 from 0.1U_16V to 1000P_50V. 4. Change PC50 from 1000P_50V to 0.1U_16V. 5. Change net +5VP and RTCVREF to VL. 6. Change PR113 from 47K_0402_5% to 0_0402_5%. 7. De-pop PC111 and change PC158 from 0.1U_16V to 0.47U_16V.	0.3	ST
20	Power rating of 0.02_2010 is not enough.	rating power of 0.02_2010 is 0.5W that is very poor for 90W adpater	0.2H	35	1. Change PR65 from 0.02_2010_1% to 0.02_2512_1%.	0.3	ST
21	Power open issue	Change size of thermal resistor and cost down	0.2H	36	Change PH1 from 10K_0805_1% to 10K_0603_1%.	0.3	ST
22	Power good giltch issue in ISL6225	The giltch occurs while secondary PWM is enabled that effects system boots up	0.2H	38	1. Add PR31 1K_0402_5%.. 2. De-pop PR294	0.3	ST
23	Fix open issue #137	DELL don't aprove item22 solution, prefer using new version ISL6225	0.2J	38	1. De-pop PR31 1K_0402_5%. 2. De-pop PR294 0_0402_5%. 3. Add PR30 0_0402_5%.	0.3	ST
24	Fix open issue #124	Fix open issue #124 and using ISL6219A	0.2J	40	1. Change PR232 from 10K_0603_5% to 5.1_0603_5%. 2. Populate PR251 and PR270 5.1_0603_5%. 3. Populate PC183 and PC194 0.01U_0603_50V. 4. De-pop PQ82,PD31,PD,32	0.3	ST
25	Fix ISN fail issue	Fix ISN fail with 200KHz	0.2J	35	1. Change PR81 from 66.5K_0603_1% to 47K_0603_1% 2. Change PC55 and PC56 from 4.7U_1210_25V to 10U_1210_25V 3. Change PL9 from 15UH to 22UH	0.3	ST
26	Fix open issue #123	Rds(on) of SI4835DY is too high,change PQ14,15,16 to SI4825DY for power stress	0.2J	35	Change PQ14,PQ15,and PQ16 from SI4835DY to SI4825DY	0.3	ST
27	Adapter shut down while running P4MaxPower 100%	Adapter current over 5.5A 4 sec while running P4MaxPower 100%	0.3	37	1. add PR303, PR306 47K_0402_1%. 2. add PR304 1M_0402_1%. 3. add PR305 226K_0402_1% 4. add PR307 147K_0402_1% 5. add PR308 100K_0402_1% 6. add PC236 0.01U_0603_50V 7. add PC239 0.1U_0603_16V 8. add PC238 1000P_0402_50V 9. add PQ83, PQ84 2N7002 10. add PU21 LM393A	0.3	ST
28	Modify thermal protect temp. from 95C to 87C	Based on thermal team requirement	0.3A	36	1. ChangePR119 from 21K_0603_1% to 17.8K_0603_1% 2. Change PR117 from 1.74K_0603_1% to 2.05K_0603_1%	0.3	ST

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Item	Fixed Issue	Reason for change	Rev.	PG #	Modify List	B.Ver #	Phase
29	modify compension for reduce output capacitor	modify compension for reduce output capacitor	0.3A	40	1. De-pop PR257 and PC179. 2. Change PC171 from 5.6N_0603_50V to 15N_0603_50V 3. Change PC172 form 47P_0603_50V to 150P_0603_50V 4. Change PR249 from 7.5K_0603_1% to 10K_0603_1%	0.3	ST
30	Fix item25 about ISN test without changing inductor	Fix item25 about ISN test without changing inductor	0.3A	35	1. Change PL9 from 22UH_SPC-1205P-220A to 15UH_SPC-1204P-150	0.3	ST
31	Capacitor DFX issues	Component layout pad overlap (reservated for noise issue) causes some components shifting when pass the re-flow	0.3D	35 36 38 40	remove PC226, PC227, PC228, PC229, PC230, PC231, PC232, PC233, PC234, PC235	1.0	QT
32	Noise issue in B+ power	Add reservated caps. back for noise issue	0.3E	35 36 38 40	reserve PC226, PC227, PC228, PC229, PC230, PC231, PC232, PC233, PC234, PC235	1.0	QT

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